

# Addendum for New QFN Package Migration

This addendum provides the changes to the 98A case outline numbers for products covered in this book. Case outlines were changed because of the migration from gold wire to copper wire in some packages. See the table below for the old (gold wire) package versus the new (copper wire) package.

To view the new drawing, go to [Freescale.com](http://Freescale.com) and search on the new 98A package number for your device.

For more information about QFN package use, see EB806: *Electrical Connection Recommendations for the Exposed Pad on QFN and DFN Packages*.

| Part Number   | Package Description | Original (gold wire)<br>package document number | Current (copper wire)<br>package document number |
|---------------|---------------------|-------------------------------------------------|--------------------------------------------------|
| MC68HC908JW32 | 48 QFN              | 98ARH99048A                                     | 98ASA00466D                                      |
| MC9S08AC16    |                     |                                                 |                                                  |
| MC9S908AC60   |                     |                                                 |                                                  |
| MC9S08AC128   |                     |                                                 |                                                  |
| MC9S08AW60    |                     |                                                 |                                                  |
| MC9S08GB60A   |                     |                                                 |                                                  |
| MC9S08GT16A   |                     |                                                 |                                                  |
| MC9S08JM16    |                     |                                                 |                                                  |
| MC9S08JM60    |                     |                                                 |                                                  |
| MC9S08LL16    |                     |                                                 |                                                  |
| MC9S08QE128   |                     |                                                 |                                                  |
| MC9S08QE32    |                     |                                                 |                                                  |
| MC9S08RG60    |                     |                                                 |                                                  |
| MCF51CN128    |                     |                                                 |                                                  |
| MC9RS08LA8    | 48 QFN              | 98ARL10606D                                     | 98ASA00466D                                      |
| MC9S08GT16A   | 32 QFN              | 98ARH99035A                                     | 98ASA00473D                                      |
| MC9S908QE32   | 32 QFN              | 98ARE10566D                                     | 98ASA00473D                                      |
| MC9S908QE8    | 32 QFN              | 98ASA00071D                                     | 98ASA00736D                                      |
| MC9S08JS16    | 24 QFN              | 98ARL10608D                                     | 98ASA00734D                                      |
| MC9S08QB8     |                     |                                                 |                                                  |
| MC9S08QG8     | 24 QFN              | 98ARL10605D                                     | 98ASA00474D                                      |
| MC9S08SH8     | 24 QFN              | 98ARE10714D                                     | 98ASA00474D                                      |
| MC9RS08KB12   | 24 QFN              | 98ASA00087D                                     | 98ASA00602D                                      |
| MC9S08QG8     | 16 QFN              | 98ARE10614D                                     | 98ASA00671D                                      |
| MC9RS08KB12   | 8 DFN               | 98ARL10557D                                     | 98ASA00672D                                      |
| MC9S08QG8     |                     |                                                 |                                                  |
| MC9RS08KA2    | 6 DFN               | 98ARL10602D                                     | 98ASA00735D                                      |

## MCF51CN128 ColdFire Microcontroller

### Cover: MCF51CN128

The MCF51CN128 device is a low-cost, low-power, high-performance 32-bit ColdFire V1 microcontroller (MCU) featuring 10/100 BASE-T/TX fast ethernet controller (FEC), media independent interface (MII) to connect an external physical transceiver (PHY), and multi-function external bus interface.

MCF51CN128 also has multiple communication interfaces for various ethernet gateway applications. MCF51CN128 is the first ColdFire V1 device to incorporate ethernet and external bus interface along with new features to minimize power consumption and increase functionality in low-power modes.

The MCF51CN128 features the following functional units:

- 32-bit ColdFire V1 Central Processing Unit (CPU)
  - Up to 50.33 MHz ColdFire CPU from 3.6 V to 3.0 V, up to 40 MHz CPU from 3.0 V to 2.1 V, and up to 20 MHz CPU from 2.1 V to 1.8 V across temperature range of –40 °C to 85 °C
  - Provides 0.94 Dhrystone 2.1 MIPS per MHz performance when running from internal RAM (0.76 DMIPS/MHz from flash)
  - ColdFire Instruction Set Revision C (ISA\_C)
  - Support for up to 45 peripheral interrupt requests and 7 software interrupts
- On-Chip Memory
  - 128 KB Flash, 24 KB RAM
  - Flash read/program/erase over full operating voltage and temperature
  - On-chip memory aliased to create a contiguous memory space with off-chip memory
  - Security circuitry to prevent unauthorized access to Peripherals, RAM, and flash contents
- Ethernet
  - FEC—10/100 BASE-T/TX, bus-mastering fast ethernet controller with direct memory access (DMA); supports half or full duplex; operation is limited to 3.0 V to 3.6 V

## MCF51CN128



80 LQFP  
14 mm × 14 mm



64 LQFP  
10 mm × 10 mm



48 QFN  
7 mm × 7 mm

- MII—media independent interface to connect ethernet controller to external PHY; includes output clock for external PHY
- External Bus
  - Mini-FlexBus—Multi-function external bus interface; supports up to 1 MB memories, gate-array logic, simple slave device or glueless interfaces to standard chip-selected asynchronous memories
  - Programmable options: access time per chip select, burst and burst-inhibited transfers per chip select, transfer direction, and address setup and hold times
- Power-Saving Modes
  - Two low-power stop modes, one of which allows limited use of some peripherals (ADC, KBI, RTC)
  - Reduced-power wait mode shuts off CPU and allows full use of all peripherals; FEC can remain active and conduct DMA transfers to RAM and assert an interrupt to wake up the CPU upon completion
  - Low-power run and wait modes allow peripherals to run while the voltage regulator is in standby
  - Peripheral clock enable register can disable clocks to unused modules, thereby reducing currents
  - Low-power external oscillator that can be used in stop3 mode to provide accurate clock source to active peripherals
  - Low-power real-time counter for use in run, wait, and stop modes with internal and external clock sources
  - 6 μs typical wake-up time from stop3 mode
  - Pins and clocks to peripherals not available in smaller packages are automatically disabled for reduced current consumption; no user interaction is needed
- Clock Source Options
  - Oscillator (XOSC) — Loop-control pierce oscillator; crystal or ceramic resonator range of 31.25 kHz to 38.4 kHz or 1 MHz to 25 MHz
  - Multi-Purpose Clock Generator (MCG) — Flexible clock source module with either frequency-locked-loop (FLL) or phase-lock loop (PLL) clock options. FLL can be controlled by internal or external reference and

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includes precision trimming of internal reference, allowing 0.2% resolution and 2% deviation over temperature and voltage. PLL derives a higher accuracy clock source derived by an external reference

- System Protection
  - Watchdog computer operating properly (COP) reset with option to run from dedicated 1-kHz internal clock source or bus clock
  - Low-voltage detection with reset or interrupt; selectable trip points
  - Illegal opcode and illegal address detection with programmable reset or exception response
  - Flash block protection
- Development Support
  - Single-wire background debug module (BDM) interface; supports same electrical interface used by the S08, 9S12, and 9S12x families debug modules
  - 4 PC plus 2 address (optional data) breakpoint registers with programmable 1- or 2-level trigger response
  - 64-entry processor status and debug data trace buffer with programmable start/stop conditions
- Peripherals
  - ADC—Up to 12 channel, 12-bit resolution; 2.5  $\mu$ s conversion time; automatic compare function; 1.7 mV/°C temperature sensor; internal bandgap reference channel; operation in stop3; fully functional from 3.6 V to 1.8 V
  - SCI—Three modules with optional 13-bit break
  - SPI—Two interfaces with full-duplex or single-wire bi-directional; double-buffered transmit and receive; master or slave mode; MSB-first or LSB-first shifting
  - IIC—Two IICs with up to 100 kbps with maximum bus loading; multi-master operation; programmable slave address; interrupt-driven byte-by-byte data transfer; supports broadcast mode and 11-bit addressing
  - TPM—Two 3-channel, 16-bit resolution modules; selectable input capture, output compare, or buffered edge- or center-aligned PWM on each channel
  - RTC—8-bit modulus counter with binary- or decimal-based prescaler; external clock source for precise time base, time-of-day, calendar- or task-scheduling functions; free-running on-chip low-power oscillator (1 kHz) for cyclic wake-up without external components; runs in all MCU modes
  - MTIM—Two 8-bit resolution modulo timers with 8-bit prescaler
- Input/Output
  - Up to 70 general-purpose input/output (GPIO) pins, all with pin mux controls to select alternate functions
  - 16 keyboard interrupt (KBI) pins with selectable polarity
  - Hysteresis and configurable pull-up device or input filtering on all input pins; configurable slew rate and drive strength on all output pins
  - 16 Rapid GPIO pins connected to the CPU's high-speed local bus with set, clear, and toggle functionality (PTD and PTF)

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# 1 MCF51CN128 Series Comparison

## 1.1 Device Comparison

The following table compares the various device derivatives available within the MCF51CN128 series.

**Table 1. MCF51CN128 Series Device Comparison**

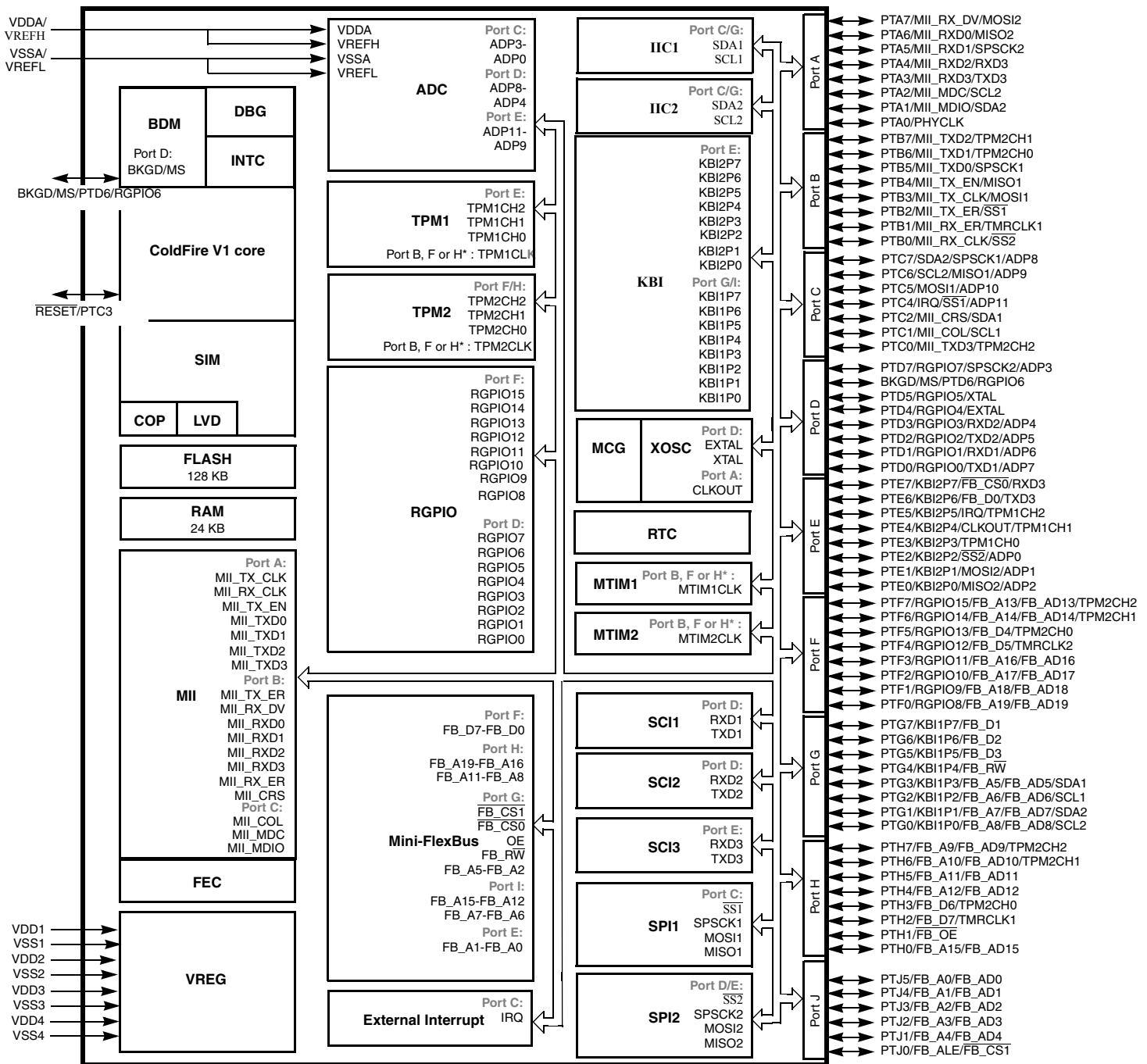
| Feature                                                                              | MCF51CN128       |        |        |
|--------------------------------------------------------------------------------------|------------------|--------|--------|
|                                                                                      | 80-pin           | 64-pin | 48-pin |
| Flash memory size (KB)                                                               | 128              |        |        |
| RAM size (KB)                                                                        | 24               |        |        |
| V1 ColdFire core equipped with BDM (background debug module) and 2X3 Crossbar switch | Yes              |        |        |
| ADC (analog-to-digital converter) channels (12-bit)                                  | 12               |        |        |
| FEC (Fast Ethernet Controller with MII Interface)                                    | Yes              |        |        |
| COP (computer operating properly)                                                    | Yes              |        |        |
| IIC1 (inter-integrated circuit)                                                      | Yes              |        |        |
| IIC2                                                                                 | Yes              |        |        |
| IRQ (interrupt request input)                                                        | Yes              |        |        |
| KBI (keyboard interrupts)                                                            | 16               | 12     | 6      |
| LVD (low-voltage detector)                                                           | Yes              |        |        |
| MCG (multipurpose clock generator)                                                   | Yes              |        |        |
| Port I/O <sup>1</sup>                                                                | 70               | 54     | 38     |
| RGPIO (rapid general-purpose I/O)                                                    | 16               | 16     | 8      |
| RTC (real-time counter)                                                              | Yes              |        |        |
| SCI1, SCI2 & SCI3 (serial communications interface)                                  | Yes              |        |        |
| SPI1 & SPI2 (serial peripheral interface)                                            | Yes              |        |        |
| TPM1 (Timer/PWM Module) channels                                                     | 3                | 3      | 3      |
| TPM2 channels                                                                        | 3                | 3      | 3      |
| MTIM1 & MTIM2                                                                        | Yes <sup>2</sup> |        |        |
| External Timer Clocks                                                                | 2                | 1      | 1      |
| Mini-FlexBus                                                                         | Yes              | 0      | 0      |
| XOSC (crystal oscillator)                                                            | Yes              |        |        |

<sup>1</sup> All GPIO are muxed with other functions

<sup>2</sup> TMRCLK2 is not available on the 48 pin package, although MTIM2 can be used as an internal timebase using on-chip clock sources.

## 1.2 Block Diagram

The following figure shows the connections between the MCF51CN128 series pins and modules.



\* TPMx and MTIMx external clocks each have the choice of being assigned to either TMRCLK1 or TMRCLK2.

Figure 1. MCF51CN128 Series Block Diagram

## 2 Pin Assignments

This section describes the pin assignments for the available packages. See for pin availability by package pin-count.

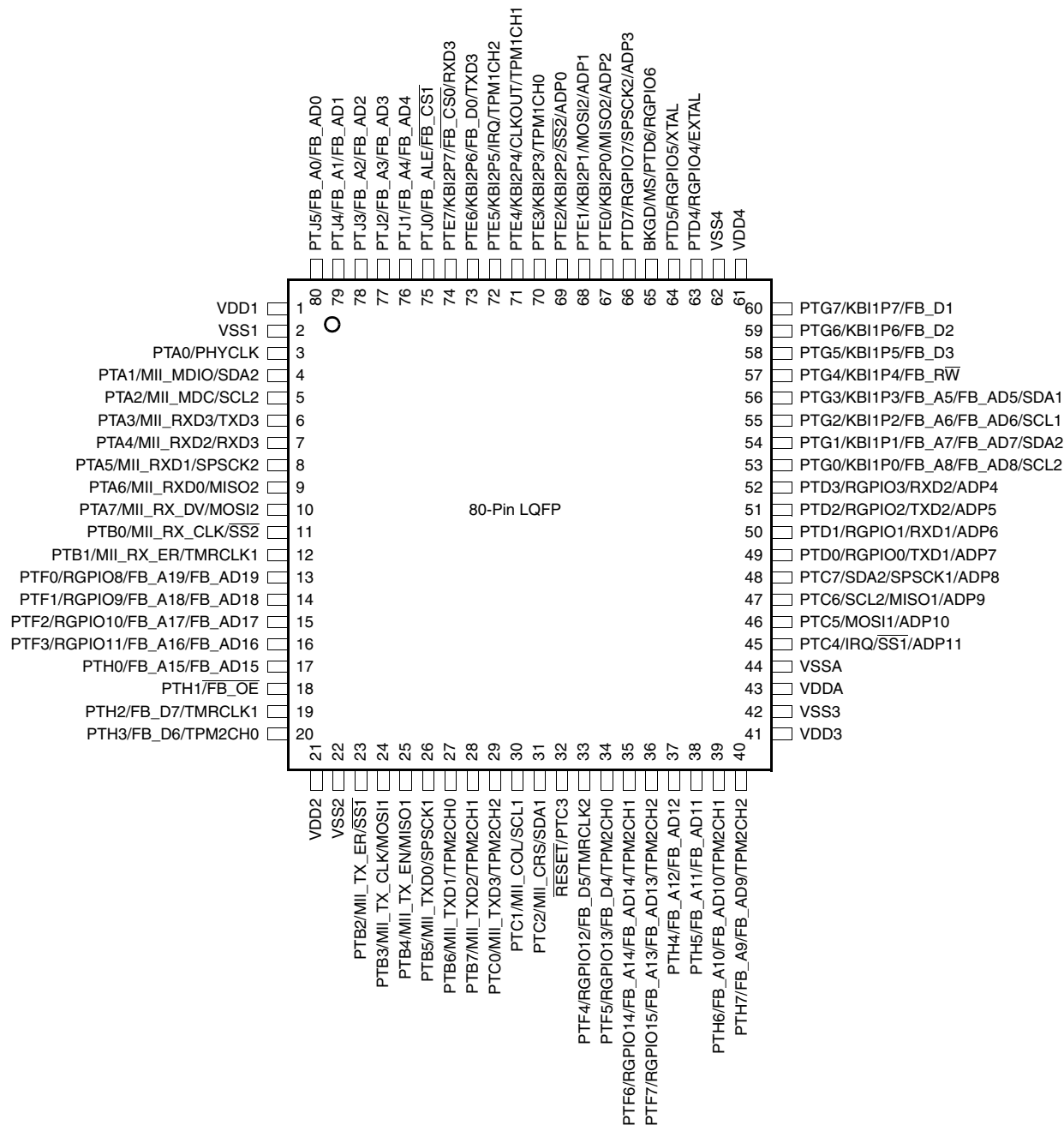


Figure 2. Pin Assignments in 80-Pin LQFP Package



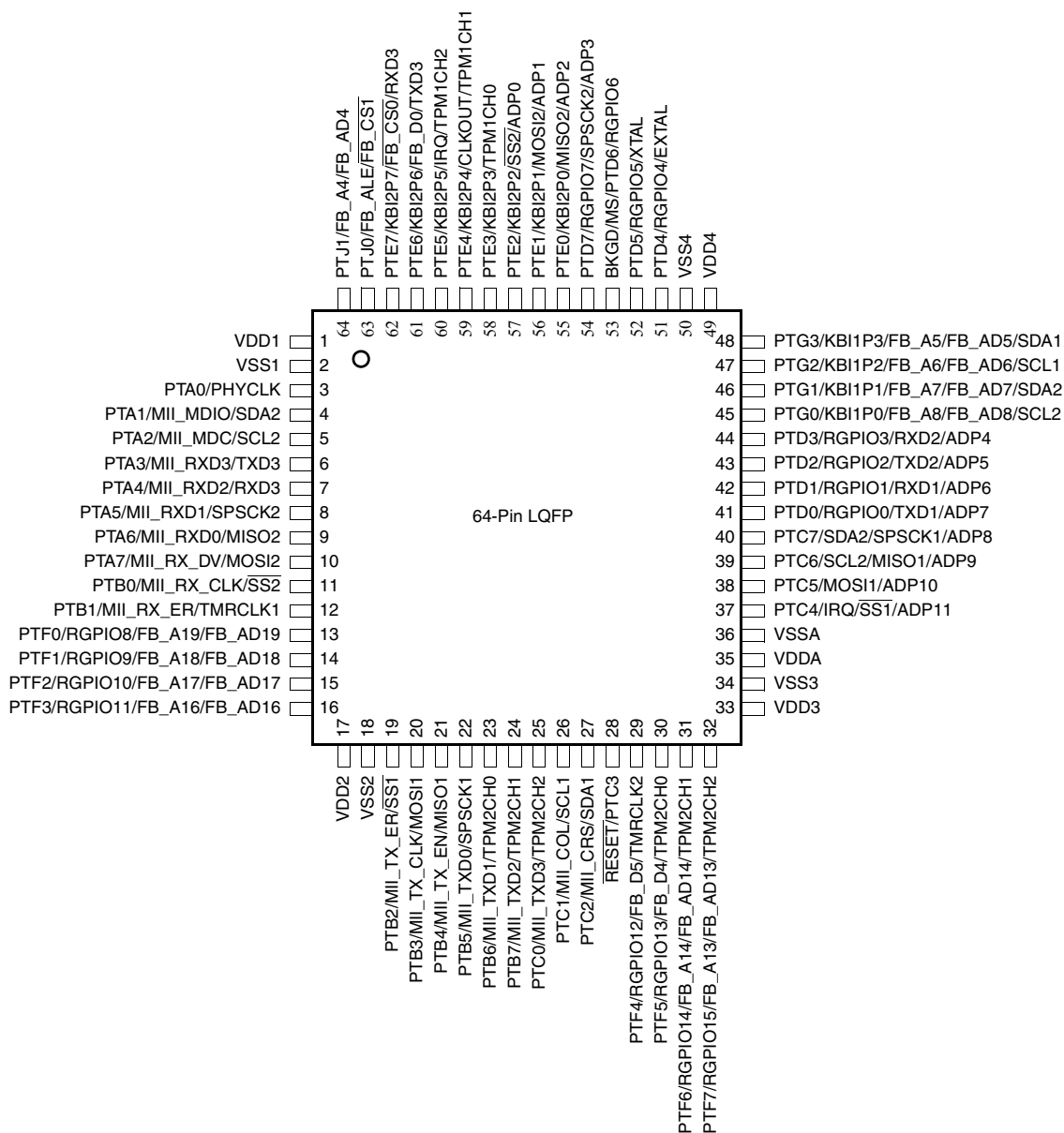
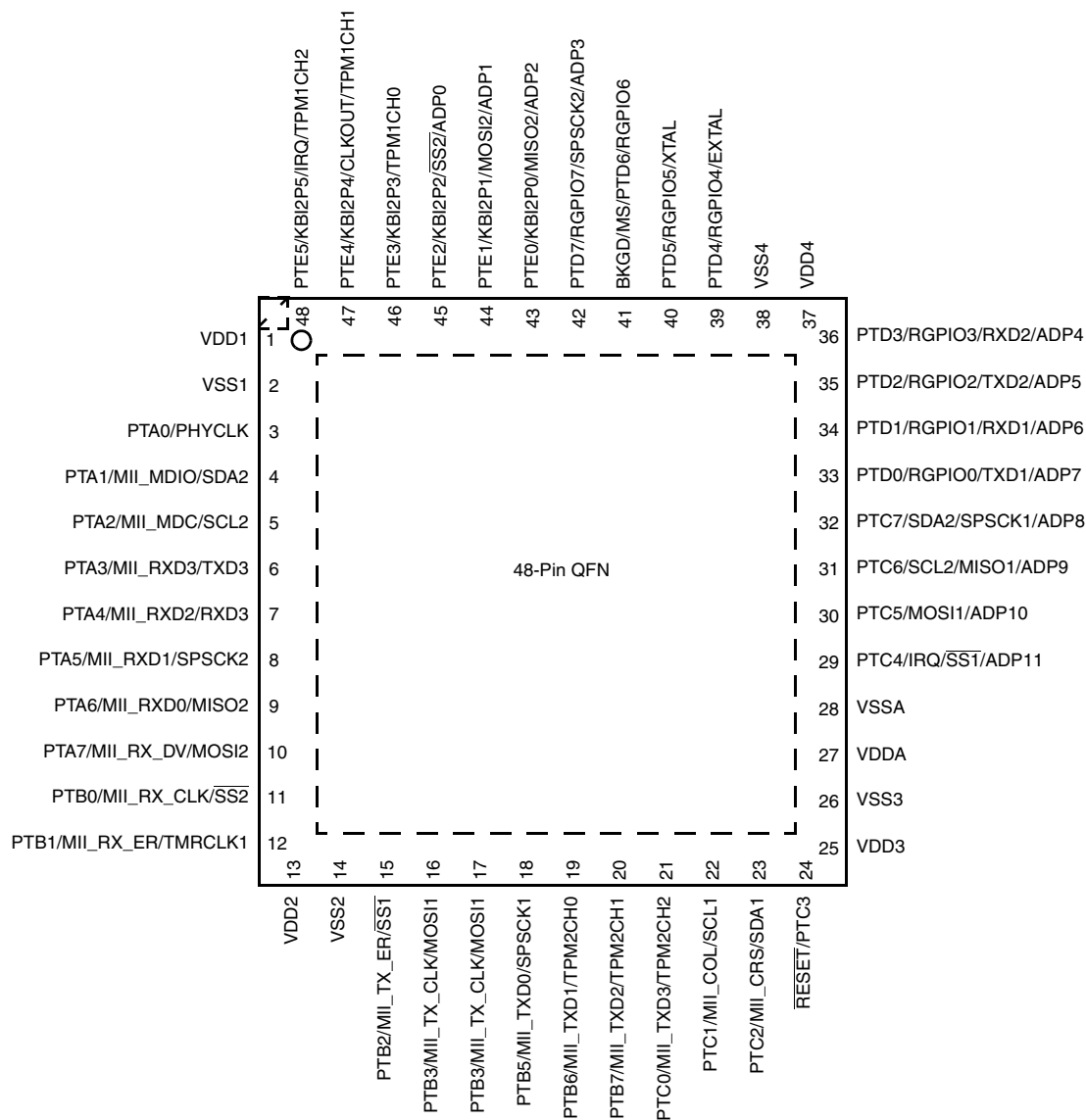


Figure 3. Pin Assignments in 64-Pin LQFP Package



**Figure 4. Pin Assignments in 48-Pin QFN Package**

## NOTE

There is no electrical connection to the flag for 48-pin QFN packages.

**Table 2. Package Pin Assignments**

| 80-Pin | 64-Pin | 48-Pin | Default Function | Alt 1  | Alt 2 | Alt 3 | Comment |
|--------|--------|--------|------------------|--------|-------|-------|---------|
| 1      | 1      | 1      | VDD1             | —      | —     | —     | —       |
| 2      | 2      | 2      | VSS1             | —      | —     | —     | —       |
| 3      | 3      | 3      | PTA0             | PHYCLK | —     | —     | —       |

Table 2. Package Pin Assignments (continued)

| 80-Pin | 64-Pin | 48-Pin | Default Function | Alt 1      | Alt 2               | Alt 3   | Comment                                           |
|--------|--------|--------|------------------|------------|---------------------|---------|---------------------------------------------------|
| 4      | 4      | 4      | PTA1             | MII_MDIO   | —                   | SDA2    | —                                                 |
| 5      | 5      | 5      | PTA2             | MII_MDC    | —                   | SCL2    | —                                                 |
| 6      | 6      | 6      | PTA3             | MII_RXD3   | TXD3                | —       | —                                                 |
| 7      | 7      | 7      | PTA4             | MII_RXD2   | RXD3                | —       | —                                                 |
| 8      | 8      | 8      | PTA5             | MII_RXD1   | SPSCK2              | —       | —                                                 |
| 9      | 9      | 9      | PTA6             | MII_RXD0   | MISO2               | —       | —                                                 |
| 10     | 10     | 10     | PTA7             | MII_RX_DV  | MOSI2               | —       | —                                                 |
| 11     | 11     | 11     | PTB0             | MII_RX_CLK | $\overline{SS}2$    | —       | —                                                 |
| 12     | 12     | 12     | PTB1             | MII_RX_ER  | —                   | TMRCLK1 | —                                                 |
| 13     | 13     | —      | PTF0/RGPIO8      | —          | FB_A19/FB_AD19      | —       | RGPIO_ENB selects between standard GPIO and RGPIO |
| 14     | 14     | —      | PTF1/RGPIO9      | —          | FB_A18/FB_AD18      | —       |                                                   |
| 15     | 15     | —      | PTF2/RGPIO10     | —          | FB_A17/FB_AD17      | —       |                                                   |
| 16     | 16     | —      | PTF3/RGPIO11     | —          | FB_A16/FB_AD16      | —       |                                                   |
| 17     | —      | —      | PTH0             | —          | FB_A15/FB_AD15      | —       | —                                                 |
| 18     | —      | —      | PTH1             | —          | $\overline{FB\_OE}$ | —       | —                                                 |
| 19     | —      | —      | PTH2             | —          | FB_D7               | TMRCLK1 | —                                                 |
| 20     | —      | —      | PTH3             | —          | FB_D6               | TPM2CH0 | —                                                 |
| 21     | 17     | 13     | VDD2             | —          | —                   | —       | —                                                 |
| 22     | 18     | 14     | VSS2             | —          | —                   | —       | —                                                 |
| 23     | 19     | 15     | PTB2             | MII_TX_ER  | $\overline{SS}1$    | —       | —                                                 |
| 24     | 20     | 16     | PTB3             | MII_TX_CLK | MOSI1               | —       | —                                                 |
| 25     | 21     | 17     | PTB4             | MII_TX_EN  | MISO1               | —       | —                                                 |
| 26     | 22     | 18     | PTB5             | MII_TXD0   | SPSCK1              | —       | —                                                 |
| 27     | 23     | 19     | PTB6             | MII_TXD1   | —                   | TPM2CH0 | —                                                 |
| 28     | 24     | 20     | PTB7             | MII_TXD2   | —                   | TPM2CH1 | —                                                 |
| 29     | 25     | 21     | PTC0             | MII_TXD3   | —                   | TPM2CH2 | —                                                 |
| 30     | 26     | 22     | PTC1             | MII_COL    | —                   | SCL1    | —                                                 |
| 31     | 27     | 23     | PTC2             | MII_CRS    | —                   | SDA1    | —                                                 |

## Table 2. Package Pin Assignments (continued)

| 80-Pin | 64-Pin | 48-Pin | Default Function          | Alt 1  | Alt 2                      | Alt 3   | Comment                                                                                                                                                        |
|--------|--------|--------|---------------------------|--------|----------------------------|---------|----------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 32     | 28     | 24     | $\overline{\text{RESET}}$ | PTC3   | —                          | —       | This pin is a bi-directional open drain pin and has an internal pullup. There is no clamp diode to VDD. DSE and SRE port controls for this bit have no effect. |
| 33     | 29     | —      | PTF4/RGPIO12              | —      | FB_D5                      | TMRCLK2 | RGPIO_ENB selects between standard GPIO and RGPIO                                                                                                              |
| 34     | 30     | —      | PTF5/RGPIO13              | —      | FB_D4                      | TPM2CH0 |                                                                                                                                                                |
| 35     | 31     | —      | PTF6/RGPIO14              | —      | FB_A14/FB_AD14             | TPM2CH1 |                                                                                                                                                                |
| 36     | 32     | —      | PTF7/RGPIO15              | —      | FB_A13/FB_AD13             | TPM2CH2 |                                                                                                                                                                |
| 37     | —      | —      | PTH4                      | —      | FB_A12/FB_AD12             | —       | —                                                                                                                                                              |
| 38     | —      | —      | PTH5                      | —      | FB_A11/FB_AD11             | —       | —                                                                                                                                                              |
| 39     | —      | —      | PTH6                      | —      | FB_A10/FB_AD10             | TPM2CH1 | —                                                                                                                                                              |
| 40     | —      | —      | PTH7                      | —      | FB_A9/FB_AD9               | TPM2CH2 | —                                                                                                                                                              |
| 41     | 33     | 25     | VDD3                      | —      | —                          | —       | —                                                                                                                                                              |
| 42     | 34     | 26     | VSS3                      | —      | —                          | —       | —                                                                                                                                                              |
| 43     | 35     | 27     | VDDA                      | —      | —                          | —       | —                                                                                                                                                              |
| 44     | 36     | 28     | VSSA                      | —      | —                          | —       | —                                                                                                                                                              |
| 45     | 37     | 29     | PTC4                      | IRQ    | $\overline{\text{SS1}}$    | ADP11   | —                                                                                                                                                              |
| 46     | 38     | 30     | PTC5                      | —      | MOSI1                      | ADP10   | —                                                                                                                                                              |
| 47     | 39     | 31     | PTC6                      | SCL2   | MISO1                      | ADP9    | —                                                                                                                                                              |
| 48     | 40     | 32     | PTC7                      | SDA2   | SPSCK1                     | ADP8    | —                                                                                                                                                              |
| 49     | 41     | 33     | PTD0/RGPIO0               | —      | TXD1                       | ADP7    | RGPIO_ENB selects between standard GPIO and RGPIO                                                                                                              |
| 50     | 42     | 34     | PTD1/RGPIO1               | —      | RXD1                       | ADP6    |                                                                                                                                                                |
| 51     | 43     | 35     | PTD2/RGPIO2               | —      | TXD2                       | ADP5    |                                                                                                                                                                |
| 52     | 44     | 36     | PTD3/RGPIO3               | —      | RXD2                       | ADP4    |                                                                                                                                                                |
| 53     | 45     | —      | PTG0                      | KBI1P0 | FB_A8/FB_AD8               | SCL2    | —                                                                                                                                                              |
| 54     | 46     | —      | PTG1                      | KBI1P1 | FB_A7/FB_AD7               | SDA2    | —                                                                                                                                                              |
| 55     | 47     | —      | PTG2                      | KBI1P2 | FB_A6/FB_AD6               | SCL1    | —                                                                                                                                                              |
| 56     | 48     | —      | PTG3                      | KBI1P3 | FB_A5/FB_AD5               | SDA1    | —                                                                                                                                                              |
| 57     | —      | —      | PTG4                      | KBI1P4 | FB_R $\overline{\text{W}}$ | —       | —                                                                                                                                                              |
| 58     | —      | —      | PTG5                      | KBI1P5 | FB_D3                      | —       | —                                                                                                                                                              |
| 59     | —      | —      | PTG6                      | KBI1P6 | FB_D2                      | —       | —                                                                                                                                                              |

Table 2. Package Pin Assignments (continued)

| 80-Pin | 64-Pin | 48-Pin | Default Function | Alt 1       | Alt 2                | Alt 3   | Comment                                                                                        |
|--------|--------|--------|------------------|-------------|----------------------|---------|------------------------------------------------------------------------------------------------|
| 60     | —      | —      | PTG7             | KBI1P7      | FB_D1                | —       | —                                                                                              |
| 61     | 49     | 37     | VDD4             | —           | —                    | —       | —                                                                                              |
| 62     | 50     | 38     | VSS4             | —           | —                    | —       | —                                                                                              |
| 63     | 51     | 39     | PTD4/RGPIO4      | —           | —                    | EXTAL   | RGPIO_ENB selects between standard GPIO and RGPIO                                              |
| 64     | 52     | 40     | PTD5/RGPIO5      | —           | —                    | XTAL    |                                                                                                |
| 65     | 53     | 41     | BKGD/MS          | PTD6/RGPIO6 | —                    | —       | This pin has an internal pullup. PTD6/RGPIO6 can only be programmed as an output. <sup>1</sup> |
| 66     | 54     | 42     | PTD7RGPIO7       | —           | SPSCK2               | ADP3    | RGPIO_ENB selects between standard GPIO and RGPIO                                              |
| 67     | 55     | 43     | PTE0             | KBI2P0      | MISO2                | ADP2    | —                                                                                              |
| 68     | 56     | 44     | PTE1             | KBI2P1      | MOSI2                | ADP1    | —                                                                                              |
| 69     | 57     | 45     | PTE2             | KBI2P2      | $\overline{SS}2$     | ADP0    | —                                                                                              |
| 70     | 58     | 46     | PTE3             | KBI2P3      | —                    | TPM1CH0 | —                                                                                              |
| 71     | 59     | 47     | PTE4             | KBI2P4      | CLKOUT               | TPM1CH1 | —                                                                                              |
| 72     | 60     | 48     | PTE5             | KBI2P5      | IRQ                  | TPM1CH2 | —                                                                                              |
| 73     | 61     | —      | PTE6             | KBI2P6      | FB_D0                | TXD3    | —                                                                                              |
| 74     | 62     | —      | PTE7             | KBI2P7      | $\overline{FB\_CS}0$ | RXD3    | —                                                                                              |
| 75     | 63     | —      | PTJ0             | FB_ALE      | $\overline{FB\_CS}1$ | —       | —                                                                                              |
| 76     | 64     | —      | PTJ1             | —           | FB_A4/FB_AD4         | —       | —                                                                                              |
| 77     | —      | —      | PTJ2             | —           | FB_A3/FB_AD3         | —       | —                                                                                              |
| 78     | —      | —      | PTJ3             | —           | FB_A2/FB_AD2         | —       | —                                                                                              |
| 79     | —      | —      | PTJ4             | —           | FB_A1/FB_AD1         | —       | —                                                                                              |
| 80     | —      | —      | PTJ5             | —           | FB_A0/FB_AD0         | —       | —                                                                                              |

<sup>1</sup> RGPIO\_ENB selects between standard GPIO and RGPIO. When PTD6 is set as RGPIO output, and "1" is driven to PTD6 via RGPIO function, a read of register RGPIODATA6 always returns a "0" because V1 RGPIO design looks for IO enable when the return value of RGPIO function reads data. As PTD6 is set to RGPIO output only, it returns "0" always to RGPIODATA6, although PTD6 pin is driven to high.

## 3 Electrical Characteristics

### 3.1 Introduction

This section contains electrical and timing specifications for the MCF51CN128 series of microcontrollers available at the time of publication.

## 3.2 Parameter Classification

The electrical parameters shown in this supplement are guaranteed by various methods. To give the customer a better understanding the following classification is used and the parameters are tagged accordingly in the tables where appropriate:

**Table 3. Parameter Classifications**

|          |                                                                                                                                                                                                                        |
|----------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| <b>P</b> | These parameters are guaranteed during production testing on each individual device.                                                                                                                                   |
| <b>C</b> | These parameters are achieved by the design characterization by measuring a statistically relevant sample size across process variations.                                                                              |
| <b>T</b> | These parameters are achieved by design characterization on a small sample size from typical devices under typical conditions unless otherwise noted. All values shown in the typical column are within this category. |
| <b>D</b> | These parameters are derived mainly from simulations.                                                                                                                                                                  |

### NOTE

The classification is shown in the column labeled “C” in the parameter tables where appropriate.

## 3.3 Absolute Maximum Ratings

Absolute maximum ratings are stress ratings only, and functional operation at the maxima is not guaranteed. Stress beyond the limits specified in Table 4 may affect device reliability or cause permanent damage to the device. For functional operating conditions, refer to the remaining tables in this section.

This device contains circuitry protecting against damage due to high static voltage or electrical fields; however, it is advised that normal precautions be taken to avoid application of any voltages higher than maximum-rated voltages to this high-impedance circuit. Reliability of operation is enhanced if unused inputs are tied to an appropriate logic voltage level (for instance, either  $V_{SS}$  or  $V_{DD}$ ) or the programmable pull-up resistor associated with the pin is enabled.

**Table 4. Absolute Maximum Ratings**

| Rating                                                                                          | Symbol    | Value                  | Unit |
|-------------------------------------------------------------------------------------------------|-----------|------------------------|------|
| Supply voltage                                                                                  | $V_{DD}$  | -0.3 to +3.8           | V    |
| Maximum current into $V_{DD}$                                                                   | $I_{DD}$  | 120                    | mA   |
| Digital input voltage                                                                           | $V_{In}$  | -0.3 to $V_{DD} + 0.3$ | V    |
| Instantaneous maximum current<br>Single pin limit (applies to all port pins) <sup>1, 2, 3</sup> | $I_D$     | ± 25                   | mA   |
| Storage temperature range                                                                       | $T_{stg}$ | -55 to 150             | °C   |

<sup>1</sup> Input must be current limited to the value specified. To determine the value of the required current-limiting resistor, calculate resistance values for positive ( $V_{DD}$ ) and negative ( $V_{SS}$ ) clamp voltages, then use the larger of the two resistance values.

<sup>2</sup> All functional non-supply pins are internally clamped to  $V_{SS}$  and  $V_{DD}$ .

<sup>3</sup> Power supply must maintain regulation within operating  $V_{DD}$  range during instantaneous and operating maximum current conditions. If positive injection current ( $V_{In} > V_{DD}$ ) is greater than  $I_{DD}$ , the injection current may flow out of  $V_{DD}$  and could result in external power supply going out of regulation. Ensure external  $V_{DD}$  load will shunt current greater than maximum injection current. This will be the greatest risk when the MCU is not consuming power. Examples are: if no system clock is present, or if the clock rate is very low (which would reduce overall power consumption).

### 3.4 Thermal Characteristics

This section provides information about operating temperature range, power dissipation, and package thermal resistance. Power dissipation on I/O pins is usually small compared to the power dissipation in on-chip logic and voltage regulator circuits, and it is user-determined rather than being controlled by the MCU design. To take  $P_{I/O}$  into account in power calculations, determine the difference between actual pin voltage and  $V_{SS}$  or  $V_{DD}$  and multiply by the pin current for each I/O pin. Except in cases of unusually high pin current (heavy loads), the difference between pin voltage and  $V_{SS}$  or  $V_{DD}$  will be very small.

**Table 5. Thermal Characteristics**

| Rating                                   |             | Symbol          | Value                                                                   | Unit |
|------------------------------------------|-------------|-----------------|-------------------------------------------------------------------------|------|
| Operating temperature range (packaged)   |             | T <sub>A</sub>  | T <sub>L</sub> to T <sub>H</sub><br>(−40 to 85 or 0 to 70) <sup>1</sup> | °C   |
| Maximum junction temperature             |             | T <sub>JM</sub> | 95                                                                      | °C   |
| Thermal resistance<br>Single-layer board |             |                 |                                                                         |      |
|                                          | 48-pin QFN  | θ <sub>JA</sub> | 81                                                                      | °C/W |
|                                          | 64-pin LQFP |                 | 69                                                                      |      |
|                                          | 80-pin LQFP |                 | 60                                                                      |      |
| Thermal resistance<br>Four-layer board   |             |                 |                                                                         |      |
|                                          | 48-pin QFN  | θ <sub>JA</sub> | 26                                                                      | °C/W |
|                                          | 64-pin LQFP |                 | 50                                                                      |      |
|                                          | 80-pin LQFP |                 | 47                                                                      |      |

<sup>1</sup> Depending on device.

The average chip-junction temperature ( $T_J$ ) in °C can be obtained from:

$$T_J = T_A + (P_D \times \theta_{JA}) \quad \text{Eqn. 1}$$

where:

$T_A$  = Ambient temperature, °C

$\theta_{JA}$  = Package thermal resistance, junction-to-ambient, °C/W

$P_D = P_{int} + P_{I/O}$

$P_{int} = I_{DD} \times V_{DD}$ , Watts — chip internal power

$P_{I/O}$  = Power dissipation on input and output pins — user determined

For most applications,  $P_{I/O} \ll P_{int}$  and can be neglected. An approximate relationship between  $P_D$  and  $T_J$  (if  $P_{I/O}$  is neglected) is:

$$P_D = K \div (T_J + 273^\circ\text{C}) \quad \text{Eqn. 2}$$

Solving Equation 1 and Equation 2 for K gives:

$$K = P_D \times (T_A + 273^\circ\text{C}) + \theta_{JA} \times (P_D)^2 \quad \text{Eqn. 3}$$

where K is a constant pertaining to the particular part. K can be determined from equation 3 by measuring  $P_D$  (at equilibrium) for a known  $T_A$ . Using this value of K, the values of  $P_D$  and  $T_J$  can be obtained by solving Equation 1 and Equation 2 iteratively for any value of  $T_A$ .

### 3.5 ESD Protection and Latch-Up Immunity

Although damage from electrostatic discharge (ESD) is much less common on these devices than on early CMOS circuits, normal handling precautions should be used to avoid exposure to static discharge. Qualification tests are performed to ensure that these devices can withstand exposure to reasonable levels of static without suffering any permanent damage.

All ESD testing is in conformity with AEC-Q100 Stress Test Qualification for Automotive Grade Integrated Circuits. During the device qualification ESD stresses were performed for the human body model (HBM), the machine model (MM) and the charge device model (CDM).

A device is defined as a failure if after exposure to ESD pulses the device no longer meets the device specification. Complete DC parametric and functional testing is performed per the applicable device specification at room temperature followed by hot temperature, unless specified otherwise in the device specification.

**Table 6. ESD and Latch-up Test Conditions**

| Model      | Description                 | Symbol | Value | Unit     |
|------------|-----------------------------|--------|-------|----------|
| Human Body | Series resistance           | R1     | 1500  | $\Omega$ |
|            | Storage capacitance         | C      | 100   | pF       |
|            | Number of pulses per pin    | —      | 3     |          |
| Machine    | Series resistance           | R1     | 0     | $\Omega$ |
|            | Storage capacitance         | C      | 200   | pF       |
|            | Number of pulses per pin    | —      | 3     |          |
| Latch-up   | Minimum input voltage limit | —      | – 2.5 | V        |
|            | Maximum input voltage limit | —      | 7.5   | V        |

**Table 7. ESD and Latch-Up Protection Characteristics**

| No. | Rating <sup>1</sup>                       | Symbol           | Min    | Max | Unit |
|-----|-------------------------------------------|------------------|--------|-----|------|
| 1   | Human body model (HBM)                    | V <sub>HBM</sub> | ± 2000 | —   | V    |
| 2   | Machine model (MM)                        | V <sub>MM</sub>  | ± 200  | —   | V    |
| 3   | Charge device model (CDM)                 | V <sub>CDM</sub> | ± 500  | —   | V    |
| 4   | Latch-up current at T <sub>A</sub> = 85°C | I <sub>LAT</sub> | ± 100  | —   | mA   |

<sup>1</sup> Parameter is achieved by design characterization on a small sample size from typical devices under typical conditions unless otherwise noted.



## 3.6 DC Characteristics

This section includes information about power supply requirements and I/O pin characteristics.

**Table 8. DC Characteristics**

| Num | C | Characteristic                                                                                     | Symbol                  | Condition                             | Min                  | Typ <sup>1</sup> | Max                  | Unit       |
|-----|---|----------------------------------------------------------------------------------------------------|-------------------------|---------------------------------------|----------------------|------------------|----------------------|------------|
| 1   | — | Operating Voltage <sup>2</sup>                                                                     | —                       | —                                     | 1.8 <sup>3</sup>     | —                | 3.6                  | V          |
| 2   | C | Output high voltage<br>All I/O pins,<br>low-drive strength<br>All I/O pins,<br>high-drive strength | $V_{OH}$                | 1.8 V, $I_{Load} = -2$ mA             | $V_{DD} - 0.5$       | —                | —                    | V          |
|     | P |                                                                                                    |                         | 2.7 V, $I_{Load} = -10$ mA            | $V_{DD} - 0.5$       | —                | —                    |            |
|     | T |                                                                                                    |                         | 2.3 V, $I_{Load} = -6$ mA             | $V_{DD} - 0.5$       | —                | —                    |            |
|     | C |                                                                                                    |                         | 1.8 V, $I_{Load} = -3$ mA             | $V_{DD} - 0.5$       | —                | —                    |            |
| 3   | D | Output high current<br>Max total $I_{OH}$ for all ports                                            | $I_{OHT}$               | —                                     | —                    | —                | 100                  | mA         |
| 4   | C | Output low voltage<br>All I/O pins,<br>low-drive strength<br>All I/O pins,<br>high-drive strength  | $V_{OL}$                | 1.8 V, $I_{Load} = 2$ mA              | —                    | —                | 0.5                  | V          |
|     | P |                                                                                                    |                         | 2.7 V, $I_{Load} = 10$ mA             | —                    | —                | 0.5                  |            |
|     | T |                                                                                                    |                         | 2.3 V, $I_{Load} = 6$ mA              | —                    | —                | 0.5                  |            |
|     | C |                                                                                                    |                         | 1.8 V, $I_{Load} = 3$ mA              | —                    | —                | 0.5                  |            |
| 5   | D | Output low current<br>Max total $I_{OL}$ for all ports                                             | $I_{OLT}$               | —                                     | —                    | —                | 100                  | mA         |
| 6   | P | Input high voltage<br>all digital inputs                                                           | $V_{IH}$                | $V_{DD} > 2.7$ V                      | $0.70 \times V_{DD}$ | —                | —                    | V          |
|     | C |                                                                                                    |                         | $V_{DD} > 1.8$ V                      | $0.85 \times V_{DD}$ | —                | —                    |            |
| 7   | P | Input low voltage<br>all digital inputs                                                            | $V_{IL}$                | $V_{DD} > 2.7$ V                      | —                    | —                | $0.35 \times V_{DD}$ |            |
|     | C |                                                                                                    |                         | $V_{DD} > 1.8$ V                      | —                    | —                | $0.30 \times V_{DD}$ |            |
| 8   | C | Input hysteresis<br>all digital inputs                                                             | $V_{hys}$               | —                                     | $0.06 \times V_{DD}$ | —                | —                    | mV         |
| 9   | P | Input leakage current<br>all input only pins<br>(Per pin)                                          | $I_{InI}$               | $V_{In} = V_{DD}$ or $V_{SS}$         | —                    | 0.1              | 1                    | $\mu$ A    |
| 10  | P | Hi-Z (off-state) leakage current<br>all input/output<br>(per pin)                                  | $I_{OZI}$               | $V_{In} = V_{DD}$ or $V_{SS}$         | —                    | 0.1              | 1                    | $\mu$ A    |
| 11  | P | Pull resistors<br>all digital inputs, when enabled                                                 | $R_P$                   | —                                     | 17.5                 | —                | 52.5                 | k $\Omega$ |
| 12  | D | DC injection current <sup>4, 5, 6</sup><br>Single pin limit                                        | $I_{IC}$                | $V_{IN} < V_{SS}$ , $V_{IN} > V_{DD}$ | –0.2                 | —                | 0.2                  | mA         |
|     |   | Total MCU limit, includes sum of all stressed pins                                                 |                         |                                       | –5                   | —                | 5                    | mA         |
| 13  | C | Input Capacitance, all pins                                                                        | $C_{In}$                | —                                     | —                    | —                | 8                    | pF         |
| 14  | C | POR re-arm voltage <sup>7</sup>                                                                    | $V_{POR}$               | —                                     | 0.9                  | 1.4              | 1.79                 | V          |
| 15  | D | POR re-arm time                                                                                    | $t_{POR}$               | —                                     | 10                   | —                | —                    | $\mu$ s    |
| 16  | P | Low-voltage detection threshold — high range <sup>8</sup>                                          | $V_{LVDH}$ <sup>9</sup> | $V_{DD}$ falling<br>$V_{DD}$ rising   | 2.15<br>2.24         | 2.32<br>2.39     | 2.45<br>2.49         | V          |

## Table 8. DC Characteristics (continued)

| Num | C | Characteristic                                           | Symbol     | Condition                           | Min          | Typ <sup>1</sup> | Max          | Unit |
|-----|---|----------------------------------------------------------|------------|-------------------------------------|--------------|------------------|--------------|------|
| 17  | P | Low-voltage detection threshold — low range <sup>8</sup> | $V_{LVDL}$ | $V_{DD}$ falling<br>$V_{DD}$ rising | 1.70<br>1.80 | 1.83<br>1.89     | 1.95<br>2.00 | V    |
| 18  | P | Low-voltage warning threshold — high range <sup>8</sup>  | $V_{LVWH}$ | $V_{DD}$ falling<br>$V_{DD}$ rising | 2.50<br>2.50 | 2.62<br>2.62     | 2.70<br>2.70 | V    |
| 19  | P | Low-voltage warning threshold — low range <sup>8</sup>   | $V_{LVWL}$ | $V_{DD}$ falling<br>$V_{DD}$ rising | 2.25<br>2.29 | 2.32<br>2.39     | 2.45<br>2.49 | V    |
| 20  | P | Bandgap Voltage Reference <sup>10</sup>                  | $V_{BG}$   | —                                   | 1.15         | 1.17             | 1.18         | V    |

<sup>1</sup> Typical values are measured at 25 °C. Characterized, not tested

<sup>2</sup> As an exception, the Fast Ethernet Controller (FEC) is only operational above the operating voltage of 3 V.

<sup>3</sup> As the supply voltage rises, the LVD circuit will hold the MCU in reset until the supply has risen above  $V_{LVDL}$ .

<sup>4</sup> All functional non-supply pins are internally clamped to  $V_{SS}$  and  $V_{DD}$ .

<sup>5</sup> Input must be current limited to the value specified. To determine the value of the required current-limiting resistor, calculate resistance values for positive and negative clamp voltages, then use the larger of the two values.

<sup>6</sup> Power supply must maintain regulation within operating  $V_{DD}$  range during instantaneous and operating maximum current conditions. If positive injection current ( $V_{in} > V_{DD}$ ) is greater than  $I_{DD}$ , the injection current may flow out of  $V_{DD}$  and could result in external power supply going out of regulation. Ensure external  $V_{DD}$  load will shunt current greater than maximum injection current. This will be the greatest risk when the MCU is not consuming power. Examples are: if no system clock is present, or if clock rate is very low (which would reduce overall power consumption).

<sup>7</sup> Maximum is highest voltage that POR is guaranteed.

<sup>8</sup> Low voltage detection and warning limits measured at 1 MHz bus frequency.

<sup>9</sup> Run at 1 MHz bus frequency

<sup>10</sup> Factory trimmed at  $V_{DD} = 3.3$  V, Temp = 25 °C

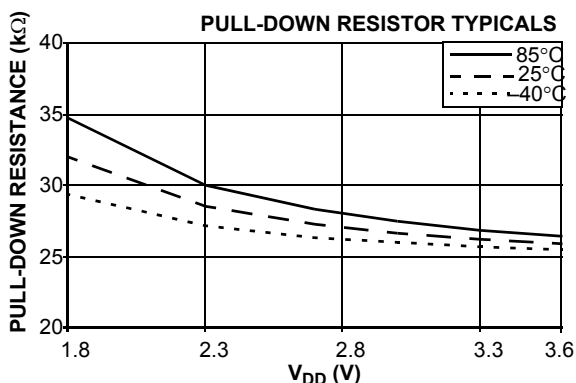
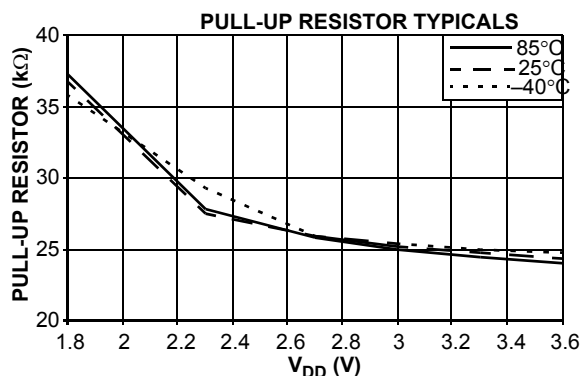


Figure 5. Pull-up and Pull-down Typical Resistor Values

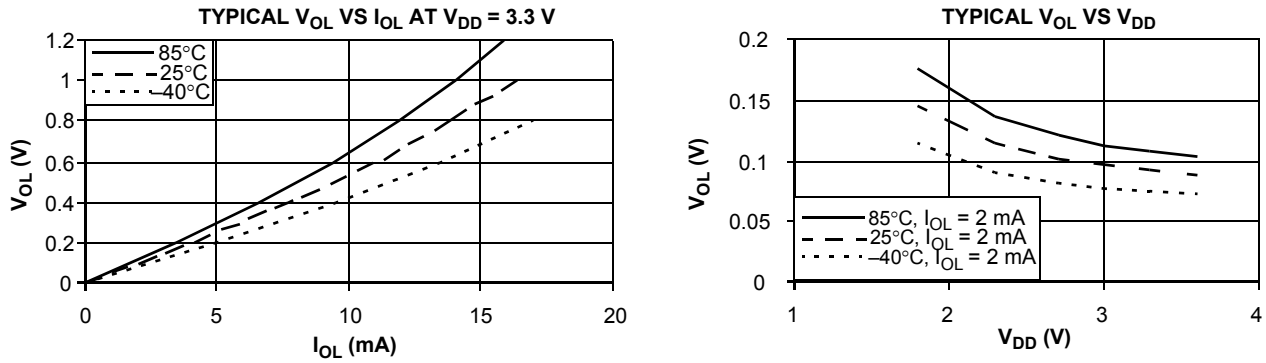


Figure 6. Typical Low-Side Driver (Sink) Characteristics — Low Drive (PTxDSn = 0)

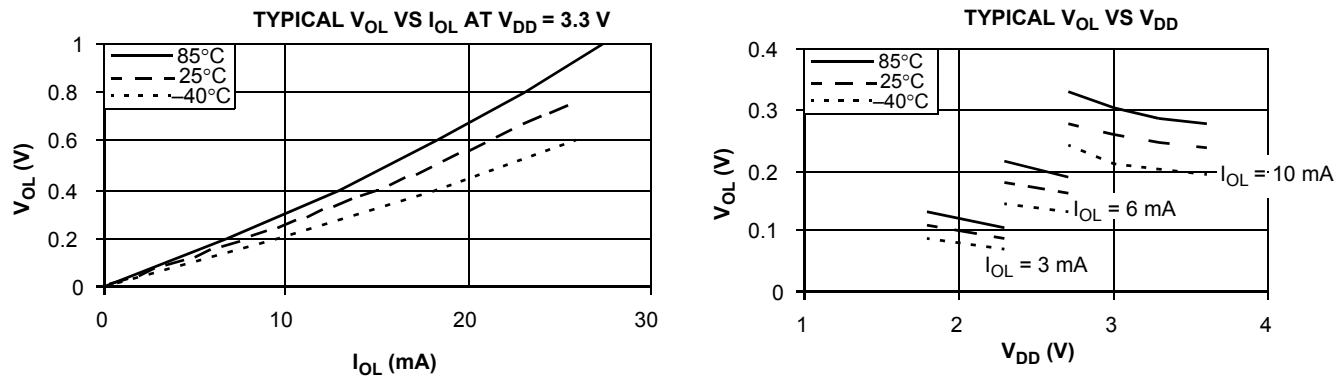


Figure 7. Typical Low-Side Driver (Sink) Characteristics — High Drive (PTxDSn = 1)

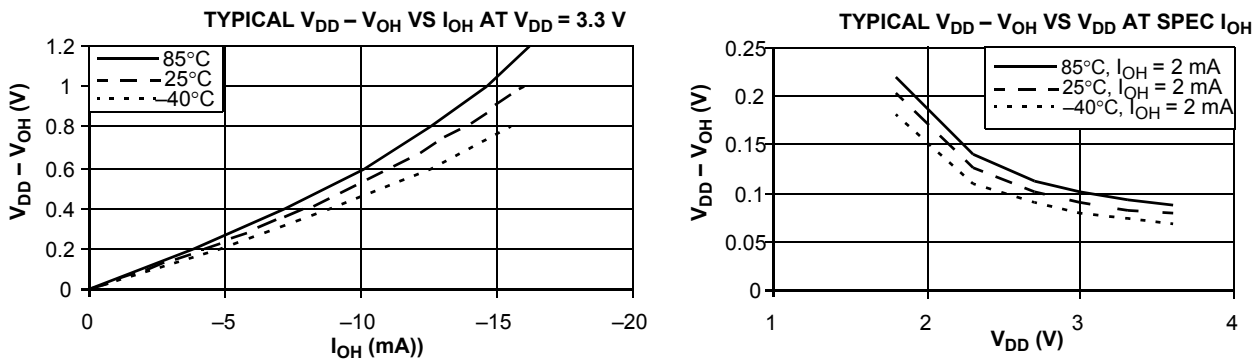


Figure 8. Typical High-Side (Source) Characteristics — Low Drive (PTxDSn = 0)

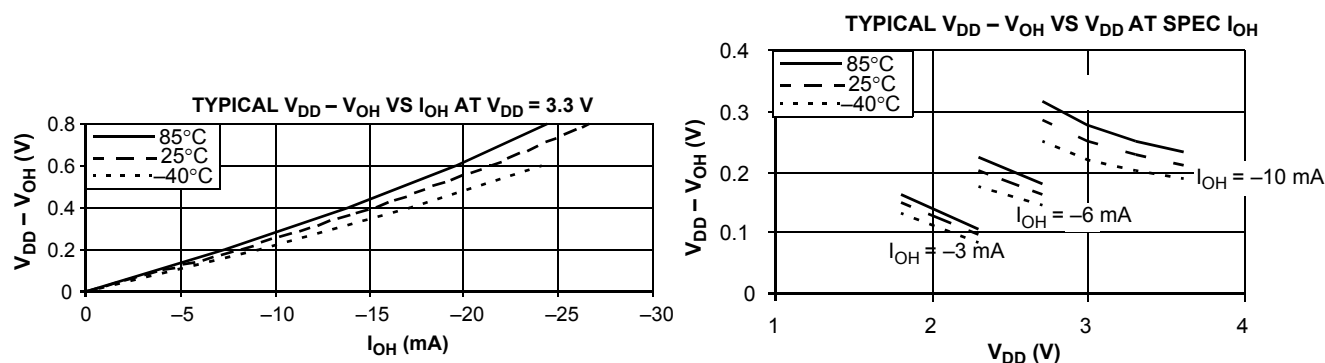


Figure 9. Typical High-Side (Source) Characteristics — High Drive (PTxDSn = 1)

## 3.7 Supply Current Characteristics

This section includes information about power supply current in various operating modes.

Table 9. Supply Current Characteristics

| Num | C | Parameter                                                            | Symbol       | Bus Freq        | $V_{DD}$ (V) | Typ <sup>1</sup> | Max  | Unit | Temp (°C)    |
|-----|---|----------------------------------------------------------------------|--------------|-----------------|--------------|------------------|------|------|--------------|
| 1   | P | Run supply current<br>FEI mode, all modules on                       | $R_{I_{DD}}$ | 25 MHz          | 3.3          | 60               | 75   | mA   | -40 to 85 °C |
|     | T |                                                                      |              | 20 MHz          |              | 49               | —    |      |              |
|     | T |                                                                      |              | 8 MHz           |              | 21               | —    |      |              |
|     | T |                                                                      |              | 1 MHz           |              | 4.6              | —    |      |              |
| 2   | C | Run supply current<br>FEI mode, all modules off                      | $R_{I_{DD}}$ | 25 MHz          | 3.3          | 44               | 47   | mA   | -40 to 85 °C |
|     | T |                                                                      |              | 20 MHz          |              | 36               | —    |      |              |
|     | T |                                                                      |              | 8 MHz           |              | 15.5             | —    |      |              |
|     | T |                                                                      |              | 1 MHz           |              | 3.9              | —    |      |              |
| 3   | T | Run supply current<br>LPRS=0, all modules off                        | $R_{I_{DD}}$ | 16 kHz<br>FBILP | 3.3          | 203              | —    | μA   | -40 to 85 °C |
|     | T |                                                                      |              | 16 kHz<br>FBELP |              | 154              | —    |      |              |
| 4   | T | Run supply current<br>LPRS=1, all modules off, running from<br>Flash | $R_{I_{DD}}$ | 16 kHz<br>FBELP | 3.3          | 50               | —    | μA   | -40 to 85 °C |
| 5   | C | Wait mode supply current<br>FEI mode, all modules off                | $W_{I_{DD}}$ | 25 MHz          | 3.3          | 11               | 13.7 | μA   | -40 to 85 °C |
|     | T |                                                                      |              | 20 MHz          |              | 4.57             | —    |      |              |
|     | T |                                                                      |              | 8 MHz           |              | 2                | —    |      |              |
|     | T |                                                                      |              | 1 MHz           |              | 0.73             | —    |      |              |
| 6   | C | Stop2 mode supply current                                            | $S2I_{DD}$   | n/a             | 3.3          | 0.35             | 11   | μA   | 0 to 70 °C   |
|     | P |                                                                      |              |                 |              |                  | 45   |      | -40 to 85 °C |
|     | C |                                                                      |              |                 | 1.8          | 0.35             | 12   |      | 0 to 70 °C   |
|     | C |                                                                      |              |                 |              |                  | 16.2 |      | -40 to 85 °C |

Table 9. Supply Current Characteristics (continued)

| Num | C | Parameter                                     |                     | Symbol            | Bus Freq | V <sub>DD</sub> (V) | Typ <sup>1</sup> | Max  | Unit | Temp (°C)    |
|-----|---|-----------------------------------------------|---------------------|-------------------|----------|---------------------|------------------|------|------|--------------|
| 7   | C | Stop3 mode supply current<br>No clocks active |                     | S3I <sub>DD</sub> | n/a      | 3.3                 | 0.52             | 14   | μA   | 0 to 70 °C   |
|     | P |                                               |                     |                   |          |                     |                  | 55   |      | −40 to 85 °C |
|     | C |                                               |                     |                   |          | 1.8                 | 0.52             | 15   |      | 0 to 70 °C   |
|     | C |                                               |                     |                   |          |                     |                  | 32.4 |      | −40 to 85 °C |
| 8   | T | Low power mode adders:                        | EREFSTEN=1          | —                 | 32 kHz   | 3.3                 | 500              | —    | nA   | −40 to 85 °C |
| 9   | T |                                               | IREFSTEN=1          |                   | 32 kHz   |                     | 70               | —    | μA   | −40 to 85 °C |
| 10  | T |                                               | TPM PWM             |                   | 100 Hz   |                     | 12               | —    | μA   | −40 to 85 °C |
| 11  | T |                                               | SCI, SPI, or IIC    |                   | 300 bps  |                     | 15               | —    | μA   | −40 to 85 °C |
| 12  | T |                                               | RTC using LPO       |                   | 1 kHz    |                     | 200              | —    | nA   | −40 to 85 °C |
| 13  | T |                                               | RTC using IC SERCLK |                   | 32 kHz   |                     | 1                | —    | μA   | −40 to 85 °C |
| 14  | T |                                               | LVD                 |                   | n/a      |                     | 100              | —    | μA   | −40 to 85 °C |

<sup>1</sup> Data in Typical column was characterized at 3.3 V, 25 °C or is typical recommended value.

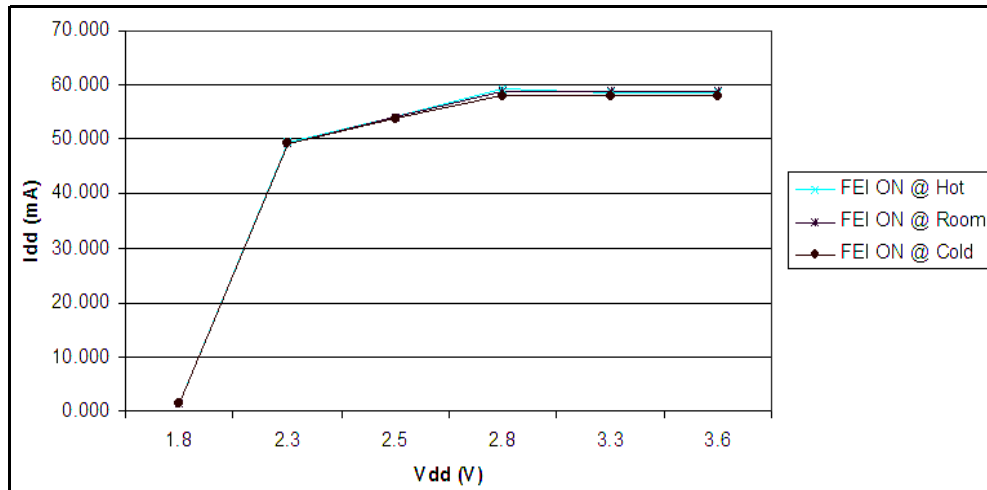


Figure 10. Typical Run I<sub>DD</sub> for FBE and FEI, I<sub>DD</sub> vs. V<sub>DD</sub>  
(ADC off, All Other Modules Enabled)

### 3.8 External Oscillator (XOSC) Characteristics

Reference Figure 11 and Figure 12 for crystal or resonator circuits.

**Table 10. XOSC and ICS Specifications (Temperature Range = –40 to 85 °C Ambient)**

| Num | C | Characteristic                                                                             | Symbol      | Min                                            | Typ <sup>1</sup> | Max            | Unit       |
|-----|---|--------------------------------------------------------------------------------------------|-------------|------------------------------------------------|------------------|----------------|------------|
| 1   | C | Oscillator crystal or resonator (EREFS = 1, ERCLKEN = 1)                                   |             |                                                |                  |                |            |
|     |   | Low range (RANGE = 0)                                                                      | $f_{lo}$    | 32                                             | —                | 38.4           | kHz        |
|     |   | High range (RANGE = 1), high gain (HGO = 1)                                                | $f_{hi}$    | 1                                              | —                | 25             | MHz        |
|     |   | High range (RANGE = 1), low power (HGO = 0)                                                | $f_{hi}$    | 1                                              | —                | 8              | MHz        |
| 2   | D | Load capacitors<br>Low range (RANGE=0), low power (HGO=0)<br>Other oscillator settings     | $C_1, C_2$  | See Note <sup>2</sup><br>See Note <sup>3</sup> |                  |                |            |
| 3   | D | Feedback resistor                                                                          | $R_F$       |                                                |                  |                |            |
|     |   | Low range, low power (RANGE=0, HGO=0) <sup>2</sup>                                         |             | —                                              | —                | —              | MΩ         |
|     |   | Low range, High Gain (RANGE=0, HGO=1)                                                      |             | —                                              | 10               | —              |            |
|     |   | High range (RANGE=1, HGO=X)                                                                |             | —                                              | 1                | —              |            |
| 4   | D | Series resistor —                                                                          | $R_S$       |                                                |                  |                |            |
|     |   | Low range, low power (RANGE = 0, HGO = 0) <sup>2</sup>                                     |             | —                                              | —                | —              | Ω          |
|     |   | Low range, high gain (RANGE = 0, HGO = 1)                                                  |             | —                                              | 0                | —              |            |
|     |   | High range, low power (RANGE = 1, HGO = 0)                                                 |             | —                                              | 100              | —              |            |
|     |   | High range, high gain (RANGE = 1, HGO = 1)                                                 |             |                                                |                  |                | KΩ         |
|     |   | ≥ 8 MHz                                                                                    |             | —                                              | 0                | 0              |            |
|     |   | 4 MHz                                                                                      |             | —                                              | 0                | 10             |            |
|     |   | 1 MHz                                                                                      |             | —                                              | 0                | 20             |            |
| 5   | C | Crystal start-up time <sup>4</sup>                                                         |             |                                                |                  |                |            |
|     |   | Low range, low power                                                                       | $t_{CSTL}$  | —                                              | 200              | —              | ms         |
|     |   | Low range, high power                                                                      |             | —                                              | 400              | —              |            |
|     |   | High range, low power                                                                      | $t_{CSTH}$  | —                                              | 5                | —              |            |
|     |   | High range, high power                                                                     |             | —                                              | 15               | —              |            |
| 6   | D | Square wave input clock frequency (EREFS = 0, ERCLKEN = 1)                                 |             |                                                |                  |                |            |
|     |   | External with FLL / PLL enabled (FEE / PEE)<br>External with bypass (FBE.FBELP,PBE, PBELP) | $f_{extal}$ | 0.03125<br>0                                   | —<br>—           | 50.33<br>50.33 | MHz<br>MHz |

<sup>1</sup> Data in Typical column was characterized at 3.3 V, 25 °C or is typical recommended value.

<sup>2</sup> Load capacitors ( $C_1, C_2$ ), feedback resistor ( $R_F$ ) and series resistor ( $R_S$ ) are incorporated internally when RANGE=HGO=0.

<sup>3</sup> See crystal or resonator manufacturer's recommendation.

<sup>4</sup> Proper PC board layout procedures must be followed to achieve specifications.

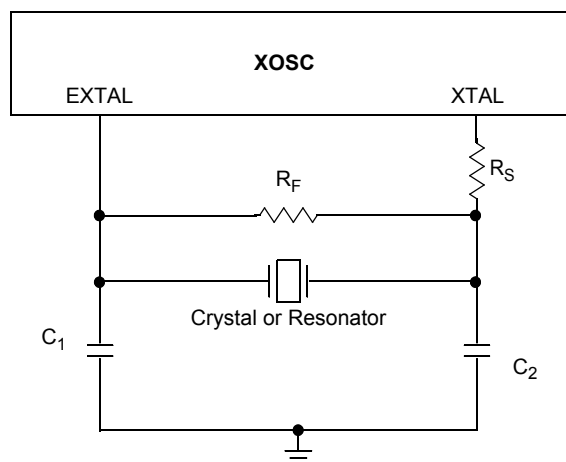


Figure 11. Typical Crystal or Resonator Circuit: High Range and Low Range/High Gain

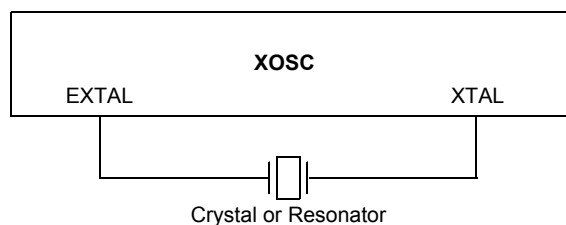


Figure 12. Typical Crystal or Resonator Circuit: Low Range/Low Gain

### 3.9 Multipurpose Clock Generator (MCG) Specifications

Table 11. MCG Frequency Specifications (Temperature Range = -40 to 125 °C Ambient)

| Num | C | Rating                                                                                                                          | Symbol                   | Min   | Typical   | Max       | Unit        |
|-----|---|---------------------------------------------------------------------------------------------------------------------------------|--------------------------|-------|-----------|-----------|-------------|
| 1   | P | Internal reference frequency - factory trimmed at $V_{DD} =$ and temperature = 25 °C                                            | $f_{int\_ft}$            | —     | 32.768    | —         | kHz         |
| 2   | P | Average internal reference frequency - untrimmed <sup>1</sup>                                                                   | $f_{int\_ut}$            | 25    | —         | 41.66     | kHz         |
| 3   | P | Average internal reference frequency - user trimmed                                                                             | $f_{int\_t}$             | 31.25 | —         | 39.06     | kHz         |
| 4   | D | Internal reference startup time                                                                                                 | $t_{irefst}$             | —     | 60        | 100       | us          |
| 5   | — | DCO output frequency range - untrimmed <sup>1</sup><br>value provided for reference:<br>$f_{dco\_ut} = 1024 \times f_{int\_ut}$ | $f_{dco\_ut}$            | 25.6  | 33.48     | 42.66     | MHz         |
| 6   | P | DCO output frequency range - trimmed                                                                                            | $f_{dco\_t}$             | 32    | —         | 40        | MHz         |
| 7   | C | Resolution of trimmed DCO output frequency at fixed voltage and temperature (using FTRIM)                                       | $\Delta f_{dco\_res\_t}$ | —     | $\pm 0.1$ | $\pm 0.2$ | % $f_{dco}$ |

**Table 11. MCG Frequency Specifications (continued)(Temperature Range = –40 to 125 °C Ambient)**

| Num | C | Rating                                                                                                | Symbol                          | Min                           | Typical       | Max                                                     | Unit               |
|-----|---|-------------------------------------------------------------------------------------------------------|---------------------------------|-------------------------------|---------------|---------------------------------------------------------|--------------------|
| 8   | C | Resolution of trimmed DCO output frequency at fixed voltage and temperature (not using FTRIM)         | $\Delta f_{\text{dco\_res\_t}}$ | —                             | $\pm 0.2$     | $\pm 0.4$                                               | % $f_{\text{dco}}$ |
| 9   | P | Total deviation of trimmed DCO output frequency over voltage and temperature                          | $\Delta f_{\text{dco\_t}}$      | —                             | + 0.5<br>-1.0 | $\pm 2$                                                 | % $f_{\text{dco}}$ |
| 10  | C | Total deviation of trimmed DCO output frequency over fixed voltage and temperature range of 0 - 70 °C | $\Delta f_{\text{dco\_t}}$      | —                             | $\pm 0.5$     | $\pm 1$                                                 | % $f_{\text{dco}}$ |
| 11  | C | FLL acquisition time <sup>2</sup>                                                                     | $t_{\text{fll\_acquire}}$       | —                             | —             | 1                                                       | ms                 |
| 12  | D | PLL acquisition time <sup>3</sup>                                                                     | $t_{\text{pll\_acquire}}$       | —                             | —             | 1                                                       | ms                 |
| 13  | C | Long term Jitter of DCO output clock (averaged over 2ms interval) <sup>4</sup>                        | $C_{\text{Jitter}}$             | —                             | 0.02          | 0.2                                                     | % $f_{\text{dco}}$ |
| 14  | D | VCO operating frequency                                                                               | $f_{\text{vco}}$                | 7.0                           | —             | 55.0                                                    | MHz                |
| 15  | D | Lock entry frequency tolerance <sup>5</sup>                                                           | $D_{\text{lock}}$               | $\pm 1.49$                    | —             | $\pm 2.98$                                              | %                  |
| 16  | D | Lock exit frequency tolerance <sup>6</sup>                                                            | $D_{\text{unl}}$                | $\pm 4.47$                    | —             | $\pm 5.97$                                              | %                  |
| 17  | D | Lock time - FLL                                                                                       | $t_{\text{fll\_lock}}$          | —                             | —             | $t_{\text{fll\_acquire}} + 1075(1/f_{\text{int\_t}})$   | s                  |
| 18  | D | Lock time - PLL                                                                                       | $t_{\text{pll\_lock}}$          | —                             | —             | $t_{\text{pll\_acquire}} + 1075(1/f_{\text{pll\_ref}})$ | s                  |
| 19  | D | Loss of external clock minimum frequency - RANGE = 0                                                  | $f_{\text{loc\_low}}$           | $(3/5) \times f_{\text{int}}$ | —             | —                                                       | kHz                |

<sup>1</sup> TRIM register at default value (0x80) and FTRIM control bit at default value (0x0).

<sup>2</sup> This specification applies to any time the FLL reference source or reference divider is changed, trim value changed or changing from FLL disabled (BLPE, BLPI) to FLL enabled (FEI, FEE, FBE, FBI). If a crystal/resonator is being used as the reference, this specification assumes it is already running.

<sup>3</sup> This specification applies to any time the PLL VCO divider or reference divider is changed, or changing from PLL disabled (BLPE, BLPI) to PLL enabled (PBE, PEE). If a crystal/resonator is being used as the reference, this specification assumes it is already running.

<sup>4</sup> Jitter is the average deviation from the programmed frequency measured over the specified interval at maximum  $f_{\text{BUS}}$ . Measurements are made with the device powered by filtered supplies and clocked by a stable external clock signal. Noise injected into the FLL circuitry via  $V_{\text{DD}}$  and  $V_{\text{SS}}$  and variation in crystal oscillator frequency increase the  $C_{\text{Jitter}}$  percentage for a given interval.

<sup>5</sup> Below  $D_{\text{lock}}$  minimum, the MCG is guaranteed to enter lock. Above  $D_{\text{lock}}$  maximum, the MCG does not enter lock. But if the MCG is already in lock, then the MCG may stay in lock.

<sup>6</sup> Below  $D_{\text{unl}}$  minimum, the MCG does not exit lock if already in lock. Above  $D_{\text{unl}}$  maximum, the MCG is guaranteed to exit lock.



### 3.10 Mini-FlexBus Timing Specifications

A multi-function external bus interface called Mini-FlexBus is provided with basic functionality to interface to slave-only devices up to a maximum bus frequency of 25.1666 MHz. It can be directly connected to asynchronous or synchronous devices such as external boot ROMs, flash memories, gate-array logic, or other simple target (slave) devices with little or no additional circuitry. For asynchronous devices a simple chip-select based interface can be used.

All processor bus timings are synchronous; that is, input setup/hold and output delay are given in respect to the rising edge of a reference clock, MB\_CLK. The MB\_CLK frequency is half the internal system bus frequency.

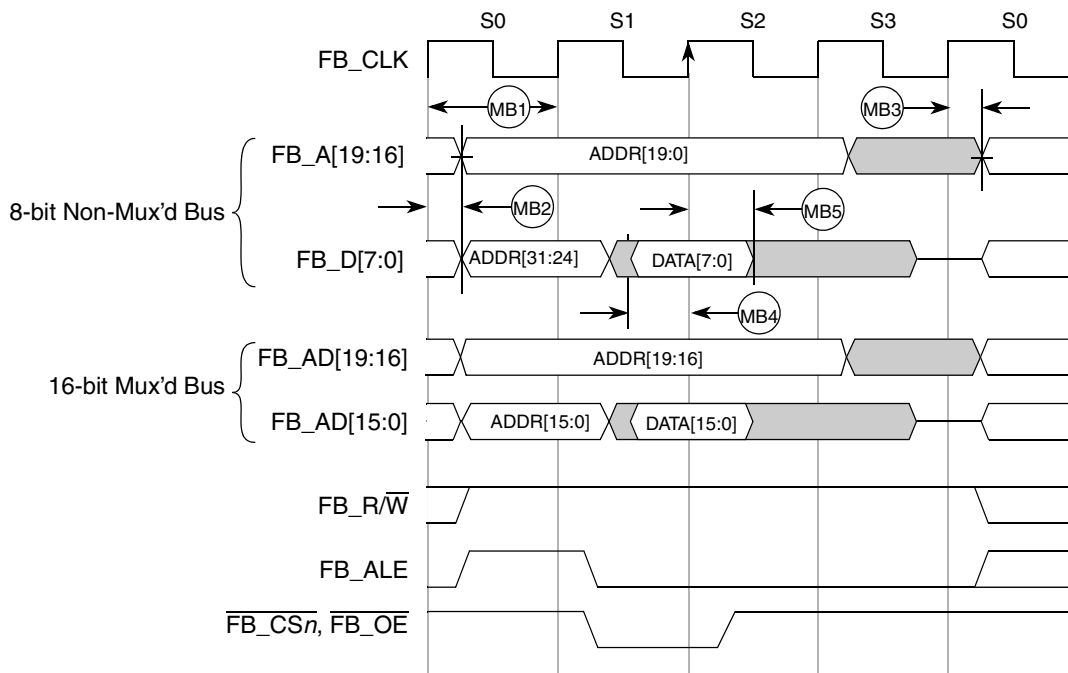
The following timing numbers indicate when data is latched or driven onto the external bus, relative to the Mini-FlexBus output clock (MB\_CLK). All other timing relationships can be derived from these values.

**Table 12. Mini-FlexBus AC Timing Specifications**

| Num | C | Characteristic         | Min   | Max     | Unit | Notes        |
|-----|---|------------------------|-------|---------|------|--------------|
| —   | — | Frequency of Operation | —     | 25.1666 | MHz  | —            |
| MB1 | D | Clock Period           | 39.73 | —       | ns   | —            |
| MB2 | P | Output Valid           | —     | 20      | ns   | <sup>1</sup> |
| MB3 | D | Output Hold            | 1.0   | —       | ns   | <sup>1</sup> |
| MB4 | P | Input Setup            | 22    | —       | ns   | <sup>2</sup> |
| MB5 | D | Input Hold             | 10    | —       | ns   | <sup>2</sup> |

<sup>1</sup> Specification is valid for all MB\_A[19:0], MB\_D[7:0], MB\_CS[1:0], MB\_OE, MB\_R/W, and MB\_ALE.

<sup>2</sup> Specification is valid for all MB\_D[7:0].



**Figure 13. Mini-FlexBus Read Timing**

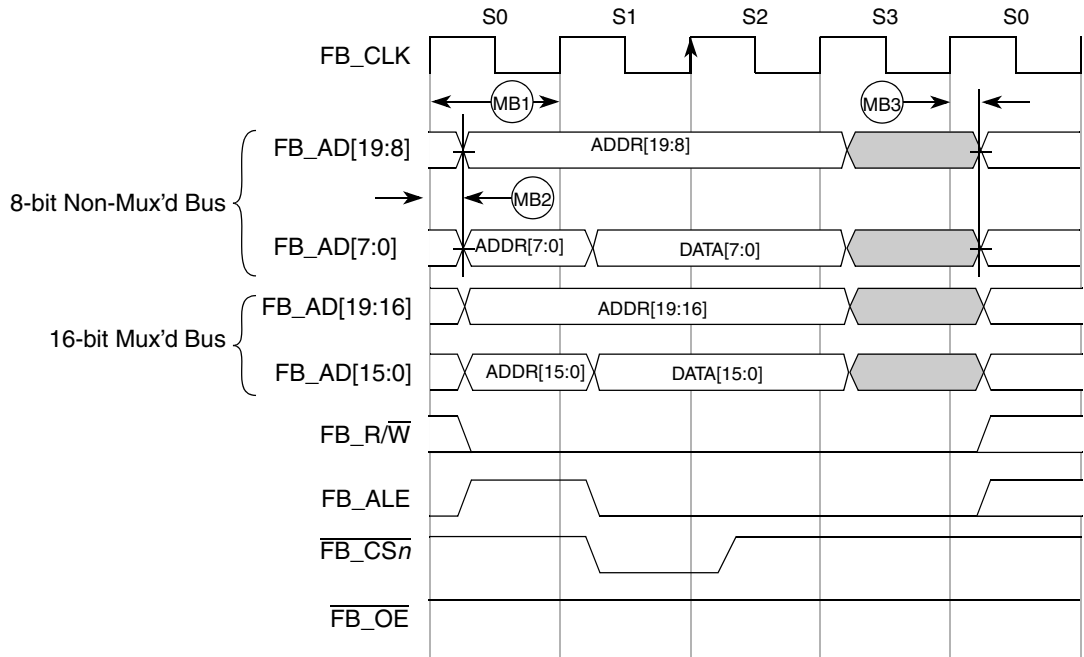


Figure 14. Mini-FlexBus Write Timing

### 3.11 Fast Ethernet Timing Specifications

The following timing specs are defined at the chip I/O pin and must be translated appropriately to arrive at timing specs/constraints for the physical interface.

#### 3.11.1 Receive Signal Timing Specifications

The following timing specs meet the requirements for MII and 7-Wire style interfaces for a range of transceiver devices.

Table 13. Receive Signal Timing

| Num | C | Characteristic                      | MII Mode |     | Unit         |
|-----|---|-------------------------------------|----------|-----|--------------|
|     |   |                                     | Min      | Max |              |
| —   | — | RXCLK frequency                     | —        | 25  | MHz          |
| E1  | P | RXD[3:0], RXDV, RXER to RXCLK setup | 5        | —   | ns           |
| E2  | D | RXCLK to RXD[3:0], RXDV, RXER hold  | 5        | —   | ns           |
| E3  | D | RXCLK pulse width high              | 35%      | 65% | RXCLK period |
| E4  | D | RXCLK pulse width low               | 35%      | 65% | RXCLK period |

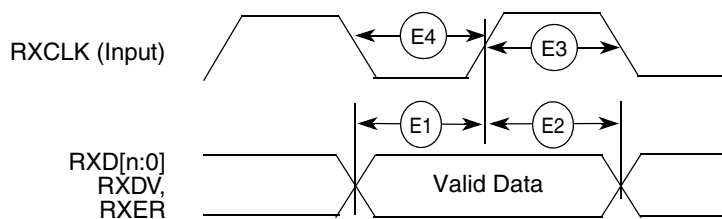


Figure 15. MII Receive Signal Timing Diagram

### 3.11.2 Transmit Signal Timing Specifications

Table 14. Transmit Signal Timing

| Num | C | Characteristic                        | MII Mode |     | Unit        |
|-----|---|---------------------------------------|----------|-----|-------------|
|     |   |                                       | Min      | Max |             |
| —   | — | TXCLK frequency                       | —        | 25  | MHz         |
| E5  | D | TXCLK to TXD[3:0], TXEN, TXER invalid | 5        | —   | ns          |
| E6  | P | TXCLK to TXD[3:0], TXEN, TXER valid   | —        | 25  | ns          |
| E7  | D | TXCLK pulse width high                | 35%      | 65% | $t_{TXCLK}$ |
| E8  | D | TXCLK pulse width low                 | 35%      | 65% | $t_{TXCLK}$ |

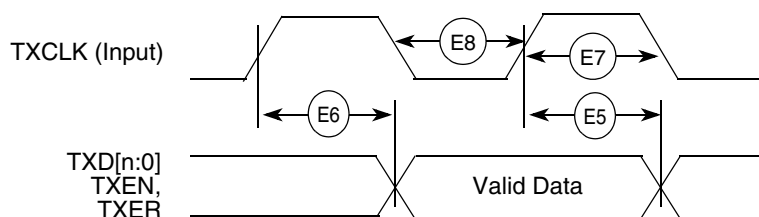


Figure 16. MII Transmit Signal Timing Diagram

### 3.11.3 Asynchronous Input Signal Timing Specifications

Table 15. MII Transmit Signal Timing

| Num | C | Characteristic               | Min | Max | Unit         |
|-----|---|------------------------------|-----|-----|--------------|
| E9  | D | CRS, COL minimum pulse width | 1.5 | —   | TXCLK period |

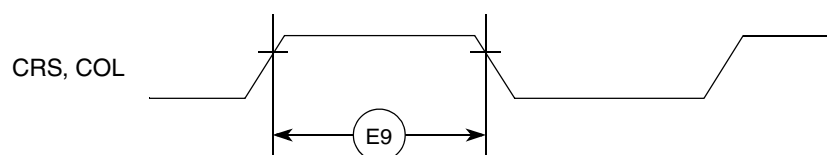


Figure 17. MII Async Inputs Timing Diagram

### 3.11.4 MII Serial Management Timing Specifications

Table 16. MII Serial Management Channel Signal Timing

| Num | C | Characteristic             | Symbol    | Min | Max | Unit        |
|-----|---|----------------------------|-----------|-----|-----|-------------|
| E10 | D | MDC cycle time             | $t_{MDC}$ | 400 | —   | ns          |
| E11 | D | MDC pulse width            | —         | 40  | 60  | % $t_{MDC}$ |
| E12 | D | MDC to MDIO output valid   | —         | —   | 375 | ns          |
| E13 | D | MDC to MDIO output invalid | —         | 30  | —   | ns          |
| E14 | D | MDIO input to MDC setup    | —         | 5   | —   | ns          |
| E15 | D | MDIO input to MDC hold     | —         | 15  | —   | ns          |

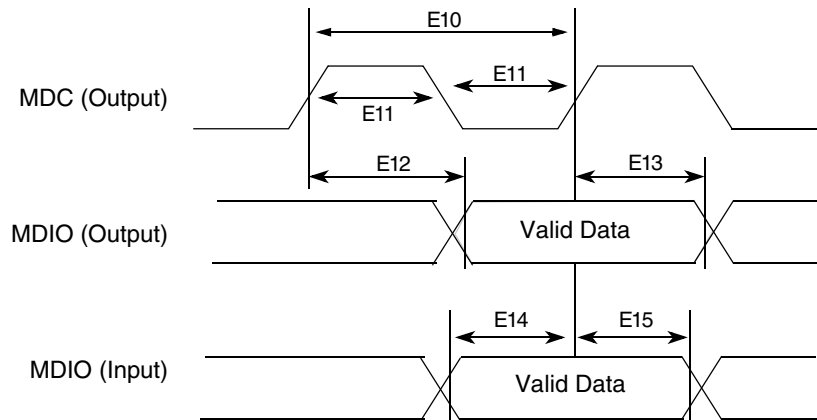


Figure 18. MII Serial Management Channel Timing Diagram

## 3.12 AC Characteristics

This section describes timing characteristics for each peripheral system.

### 3.12.1 Control Timing

Table 17. Control Timing

| Num | C | Rating                                                                                                              | Symbol       | Min                 | Typ <sup>1</sup> | Max               | Unit    |
|-----|---|---------------------------------------------------------------------------------------------------------------------|--------------|---------------------|------------------|-------------------|---------|
| 1   | D | Bus frequency ( $t_{cyc} = 1/f_{Bus}$ )<br>$V_{DD} > 2.7 V$<br>$2.7 V > V_{DD} > 2.1 V$<br>$2.1 V > V_{DD} > 1.8 V$ | $f_{Bus}$    | dc<br>dc<br>dc      | —<br>—<br>—      | 50.33<br>40<br>20 | MHz     |
| 2   | D | Internal low power oscillator period                                                                                | $t_{LPO}$    | 700                 | —                | 1300              | $\mu s$ |
| 3   | D | External reset pulse width <sup>2</sup>                                                                             | $t_{extrst}$ | 100                 | —                | —                 | ns      |
| 4   | D | Reset low drive                                                                                                     | $t_{rstdrv}$ | $34 \times t_{cyc}$ | —                | —                 | ns      |
| 5   | D | BKGD/MS setup time after issuing background debug force reset to enter user or BDM modes                            | $t_{MSSU}$   | 500                 | —                | —                 | ns      |

Table 17. Control Timing (continued)

| Num | C | Rating                                                                                                                                                                   | Symbol               | Min                       | Typ <sup>1</sup> | Max    | Unit    |
|-----|---|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------|----------------------|---------------------------|------------------|--------|---------|
| 6   | D | BKGD/MS hold time after issuing background debug force reset to enter user or BDM modes <sup>3</sup>                                                                     | $t_{MSH}$            | 100                       | —                | —      | $\mu s$ |
| 7   | D | IRQ pulse width<br>Asynchronous path <sup>2</sup><br>Synchronous path <sup>4</sup>                                                                                       | $t_{ILIH}, t_{IHIL}$ | 100<br>$2 \times t_{cyc}$ | —<br>—           | —<br>— | ns      |
| 8   | D | Keyboard interrupt pulse width<br>Asynchronous path <sup>2</sup><br>Synchronous path <sup>4</sup>                                                                        | $t_{ILIH}, t_{IHIL}$ | 100<br>$2 \times t_{cyc}$ | —<br>—           | —<br>— | ns      |
| 9   | C | Port rise and fall time —<br>Low output drive (PTxDS = 0) (load = 50 pF) <sup>5</sup><br>Slew rate control disabled (PTxSE = 0)<br>Slew rate control enabled (PTxSE = 1) | $t_{Rise}, t_{Fall}$ | —<br>—                    | 16<br>23         | —<br>— | ns      |
|     |   | Port rise and fall time —<br>High output drive (PTxDS = 1) (load = 50 pF)<br>Slew rate control disabled (PTxSE = 0)<br>Slew rate control enabled (PTxSE = 1)             | $t_{Rise}, t_{Fall}$ | —<br>—                    | 5<br>9           | —<br>— | ns      |
| 10  | C | Stop3 recovery time, from interrupt event to vector fetch                                                                                                                | $t_{STPREC}$         | —                         | 6                | 10     | $\mu s$ |

<sup>1</sup> Typical values are based on characterization data at  $V_{DD} = 3.3 V$ , 25 °C unless otherwise stated.

<sup>2</sup> This is the shortest pulse that is guaranteed to be recognized as a reset or interrupt pin request. Shorter pulses are not guaranteed to override reset requests from internal sources.

<sup>3</sup> To enter BDM mode following a POR, BKGD/MS should be held low during the power-up and for a hold time of  $t_{MSH}$  after  $V_{DD}$  rises above  $V_{LVD}$ .

<sup>4</sup> This is the minimum assertion time in which the interrupt may be recognized. The correct protocol is to assert the interrupt request until it is explicitly negated by the interrupt service routine.

<sup>5</sup> Timing is shown with respect to 20%  $V_{DD}$  and 80%  $V_{DD}$  levels. Temperature range –40 °C to 85 °C.

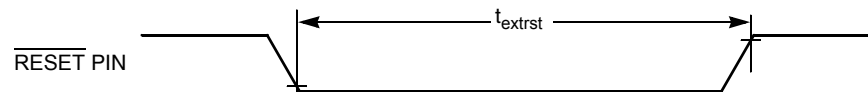
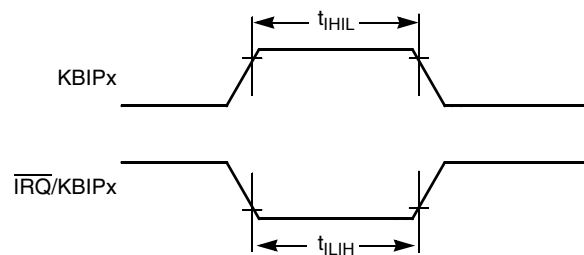


Figure 19. Reset Timing

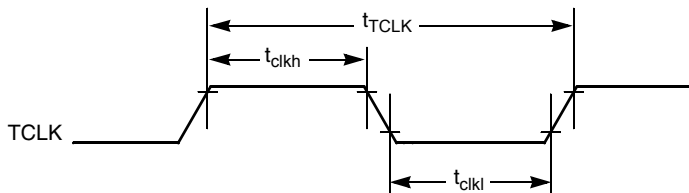

Figure 20.  $\overline{IRQ}/KBIPx$  Timing

### 3.12.2 TPM Module Timing

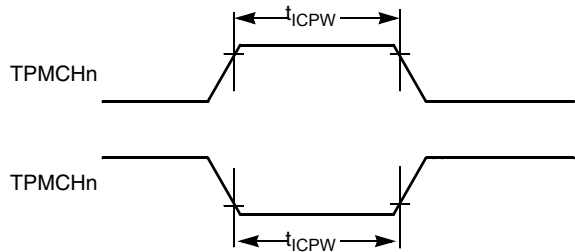
Synchronizer circuits determine the shortest input pulses that can be recognized or the fastest clock that can be used as the optional external source to the timer counter. These synchronizers operate from the current bus rate clock.

**Table 18. TPM Input Timing**

| No. | C | Function                  | Symbol     | Min | Max         | Unit      |
|-----|---|---------------------------|------------|-----|-------------|-----------|
| 1   | D | External clock frequency  | $f_{TCLK}$ | 0   | $f_{Bus}/4$ | Hz        |
| 2   | D | External clock period     | $t_{TCLK}$ | 4   | —           | $t_{cyc}$ |
| 3   | D | External clock high time  | $t_{clkh}$ | 1.5 | —           | $t_{cyc}$ |
| 4   | D | External clock low time   | $t_{clkl}$ | 1.5 | —           | $t_{cyc}$ |
| 5   | D | Input capture pulse width | $t_{ICPW}$ | 1.5 | —           | $t_{cyc}$ |



**Figure 21. Timer External Clock**



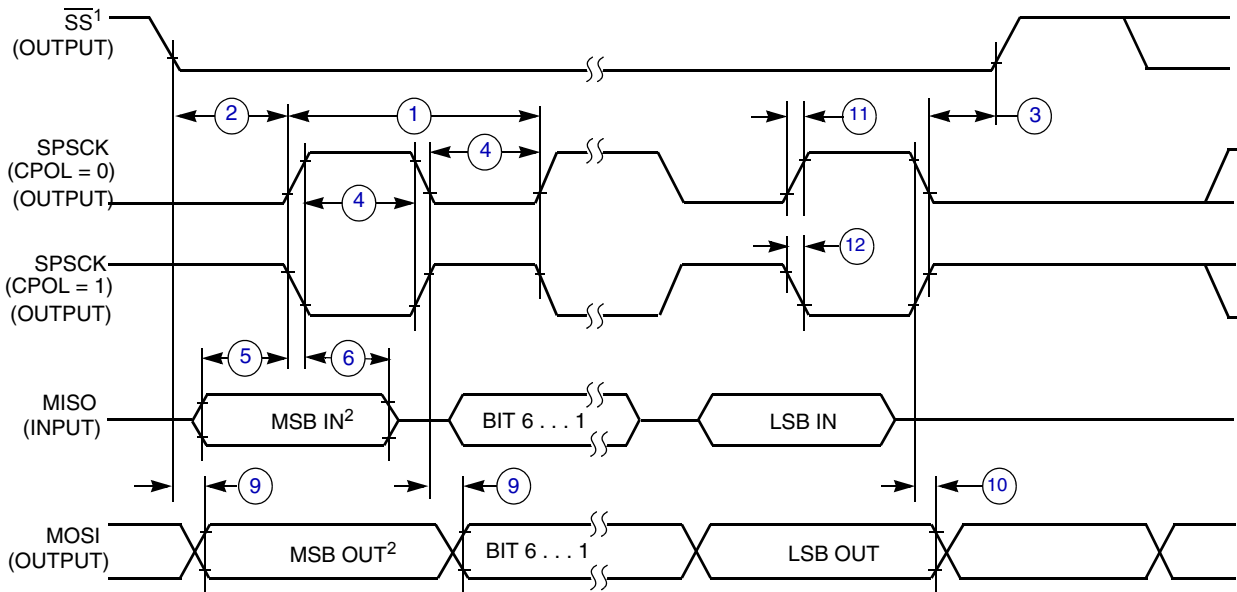
**Figure 22. Timer Input Capture Pulse**

### 3.12.3 SPI Timing

Table 19 and Figure 23 through Figure 26 describe the timing requirements for the SPI system.

**Table 19. SPI Timing**

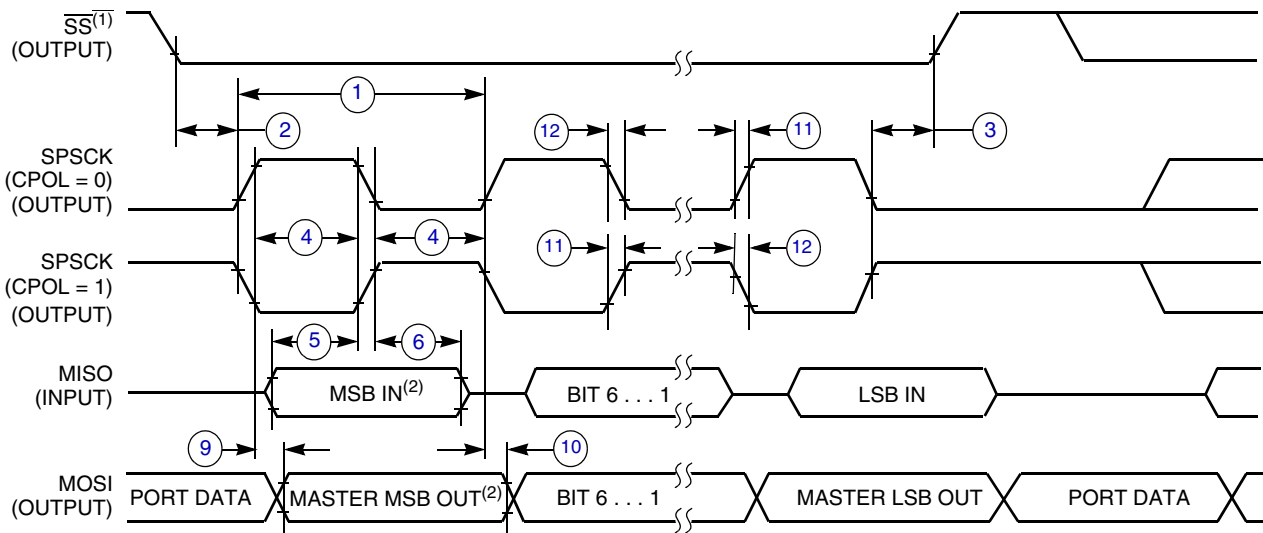
| No. | C | Function                                          | Symbol               | Min                              | Max                        | Unit                     |
|-----|---|---------------------------------------------------|----------------------|----------------------------------|----------------------------|--------------------------|
| —   | D | Operating frequency<br>Master<br>Slave            | $f_{op}$             | $f_{Bus}/2048$<br>0              | $f_{Bus}/2$<br>$f_{Bus}/4$ | Hz<br>Hz                 |
| 1   | D | SPSCK period<br>Master<br>Slave                   | $t_{SPSCK}$          | 2<br>4                           | 2048<br>—                  | $t_{cyc}$<br>$t_{cyc}$   |
| 2   | D | Enable lead time<br>Master<br>Slave               | $t_{Lead}$           | 1/2<br>1                         | —<br>—                     | $t_{SPSCK}$<br>$t_{cyc}$ |
| 3   | D | Enable lag time<br>Master<br>Slave                | $t_{Lag}$            | 1/2<br>1                         | —<br>—                     | $t_{SPSCK}$<br>$t_{cyc}$ |
| 4   | D | Clock (SPSCK) high or low time<br>Master<br>Slave | $t_{WSPSCK}$         | $t_{cyc} - 30$<br>$t_{cyc} - 30$ | $1024 t_{cyc}$<br>—        | ns<br>ns                 |
| 5   | D | Data setup time (inputs)<br>Master<br>Slave       | $t_{SU}$             | 15<br>15                         | —<br>—                     | ns<br>ns                 |
| 6   | D | Data hold time (inputs)<br>Master<br>Slave        | $t_{HI}$             | 0<br>25                          | —<br>—                     | ns<br>ns                 |
| 7   | D | Slave access time                                 | $t_a$                | —                                | 1                          | $t_{cyc}$                |
| 8   | D | Slave MISO disable time                           | $t_{dis}$            | —                                | 1                          | $t_{cyc}$                |
| 9   | D | Data valid (after SPSCK edge)<br>Master<br>Slave  | $t_v$                | —<br>—                           | 25<br>25                   | ns<br>ns                 |
| 10  | D | Data hold time (outputs)<br>Master<br>Slave       | $t_{HO}$             | 0<br>0                           | —<br>—                     | ns<br>ns                 |
| 11  | D | Rise time<br>Input<br>Output                      | $t_{RI}$<br>$t_{RO}$ | —<br>—                           | $t_{cyc} - 25$<br>25       | ns<br>ns                 |
| 12  | D | Fall time<br>Input<br>Output                      | $t_{FI}$<br>$t_{FO}$ | —<br>—                           | $t_{cyc} - 25$<br>25       | ns<br>ns                 |



**NOTES:**

1.  $\overline{SS}$  output mode (DDS7 = 1, SSOE = 1).
2. LSBF = 0. For LSBF = 1, bit order is LSB, bit 1, ..., bit 6, MSB.

**Figure 23. SPI Master Timing (CPHA = 0)**

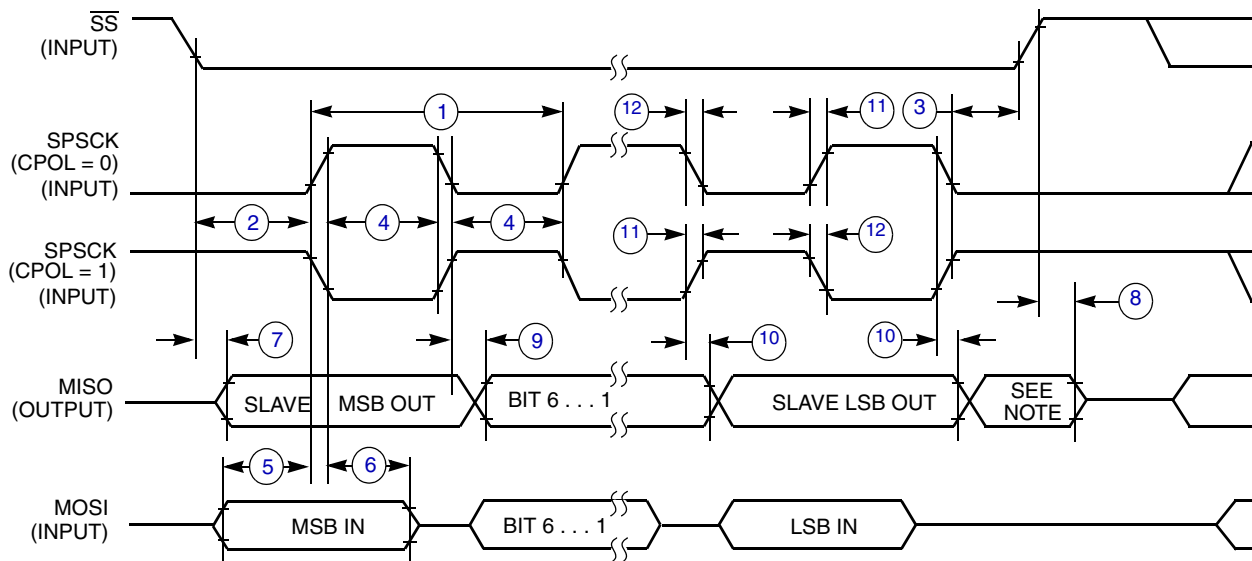


**NOTES:**

1.  $\overline{SS}$  output mode (DDS7 = 1, SSOE = 1).
2. LSBF = 0. For LSBF = 1, bit order is LSB, bit 1, ..., bit 6, MSB.

**Figure 24. SPI Master Timing (CPHA = 1)**

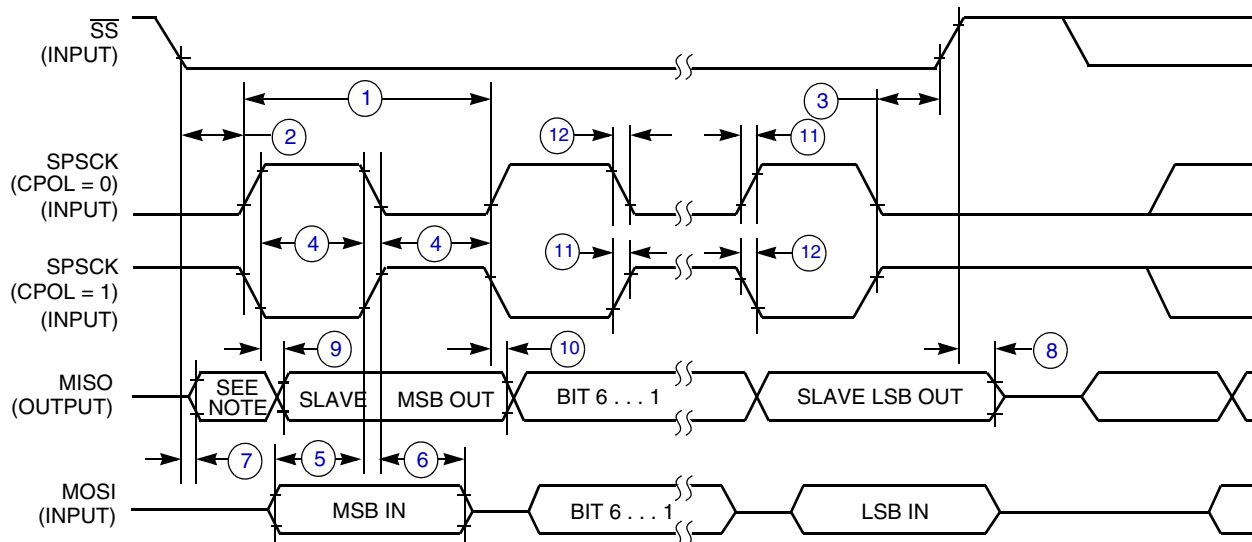




NOTE:

1. Not defined but normally MSB of character just received

**Figure 25. SPI Slave Timing (CPHA = 0)**



NOTE:

1. Not defined but normally LSB of character just received

**Figure 26. SPI Slave Timing (CPHA = 1)**

### 3.12.4 ADC Characteristics

Table 20. 12-bit ADC Operating Conditions

| C | Characteristic             | Conditions                                                          | Symb              | Min        | Typ <sup>1</sup> | Max        | Unit       | Comment         |
|---|----------------------------|---------------------------------------------------------------------|-------------------|------------|------------------|------------|------------|-----------------|
| D | Supply voltage             | Absolute                                                            | $V_{DDAD}$        | 1.8        | —                | 3.6        | V          |                 |
|   |                            | Delta to $V_{DD}$ ( $V_{DD}-V_{DDAD}$ ) <sup>2</sup>                | $\Delta V_{DDAD}$ | -100       | 0                | +100       | mV         |                 |
| D | Ground voltage             | Delta to $V_{SS}$ ( $V_{SS}-V_{SSAD}$ ) <sup>2</sup>                | $\Delta V_{SSAD}$ | -100       | 0                | +100       | mV         |                 |
| D | Ref Voltage High           |                                                                     | $V_{REFH}$        | 1.8        | $V_{DDAD}$       | $V_{DDAD}$ | V          |                 |
| D | Ref Voltage Low            |                                                                     | $V_{REFL}$        | $V_{SSAD}$ | $V_{SSAD}$       | $V_{SSAD}$ | V          |                 |
| D | Input Voltage              |                                                                     | $V_{ADIN}$        | $V_{REFL}$ | —                | $V_{REFH}$ | V          |                 |
| C | Input Capacitance          |                                                                     | $C_{ADIN}$        | —          | 4.5              | 5.5        | pF         |                 |
| C | Input Resistance           |                                                                     | $R_{ADIN}$        | —          | 5                | 7          | k $\Omega$ |                 |
| C | Analog Source Resistance   | 12 bit mode<br>$f_{ADCK} > 4\text{MHz}$<br>$f_{ADCK} < 4\text{MHz}$ | $R_{AS}$          | —<br>—     | —<br>—           | 2<br>5     | k $\Omega$ | External to MCU |
|   |                            | 10 bit mode<br>$f_{ADCK} > 4\text{MHz}$<br>$f_{ADCK} < 4\text{MHz}$ |                   | —<br>—     | —<br>—           | 5<br>10    |            |                 |
|   |                            | 8 bit mode (all valid $f_{ADCK}$ )                                  |                   | —          | —                | 10         |            |                 |
|   |                            |                                                                     |                   |            |                  |            |            |                 |
| D | ADC Conversion Clock Freq. | High Speed (ADLPC=0)                                                | $f_{ADCK}$        | 0.4        | —                | 8.0        | MHz        |                 |
|   |                            | Low Power (ADLPC=1)                                                 |                   | 0.4        | —                | 4.0        |            |                 |

<sup>1</sup> Typical values assume  $V_{DDAD} = 3.3\text{ V}$ , Temp = 25 °C,  $f_{ADCK}=1.0\text{ MHz}$  unless otherwise stated. Typical values are for reference only and are not tested in production.

<sup>2</sup> DC potential difference.

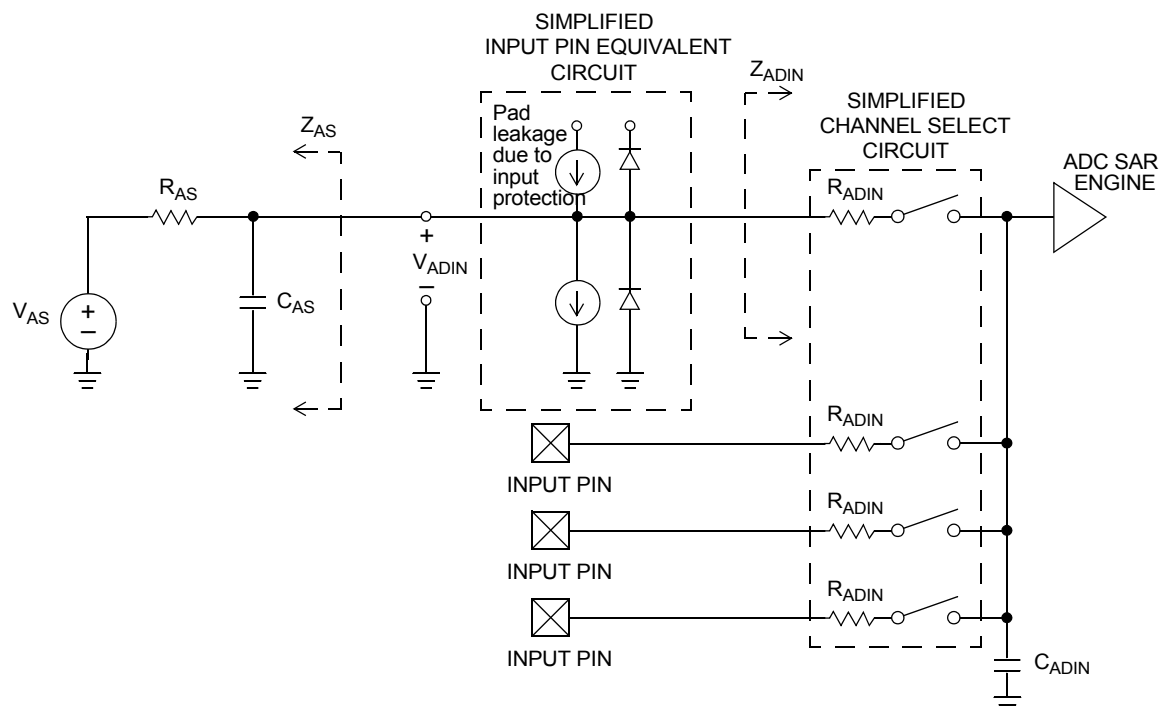


Figure 27. ADC Input Impedance Equivalency Diagram

Table 21. 12-bit ADC Characteristics ( $V_{REFH} = V_{DDAD}$ ,  $V_{REFL} = V_{SSAD}$ )

| Characteristic                                  | Conditions              | C | Symb        | Min  | Typ <sup>1</sup> | Max | Unit    | Comment                   |
|-------------------------------------------------|-------------------------|---|-------------|------|------------------|-----|---------|---------------------------|
| Supply Current<br>ADLPC=1<br>ADLSMP=1<br>ADCO=1 |                         | T | $I_{DDAD}$  | —    | 120              | —   | $\mu A$ |                           |
| Supply Current<br>ADLPC=1<br>ADLSMP=0<br>ADCO=1 |                         | T | $I_{DDAD}$  | —    | 202              | —   | $\mu A$ |                           |
| Supply Current<br>ADLPC=0<br>ADLSMP=1<br>ADCO=1 |                         | T | $I_{DDAD}$  | —    | 288              | —   | $\mu A$ |                           |
| Supply Current<br>ADLPC=0<br>ADLSMP=0<br>ADCO=1 |                         | T | $I_{DDAD}$  | —    | 0.532            | 1   | mA      |                           |
| Supply Current                                  | Stop, Reset, Module Off | D | $I_{DDAD}$  | —    | 0.007            | 0.8 | $\mu A$ |                           |
| ADC<br>Asynchronous<br>Clock Source             | High Speed (ADLPC=0)    | P | $f_{ADACK}$ | 2    | 3.3              | 5   | MHz     | $t_{ADACK} = 1/f_{ADACK}$ |
|                                                 | Low Power (ADLPC=1)     | C |             | 1.25 | 2                | 3.3 |         |                           |

**Table 21. 12-bit ADC Characteristics ( $V_{REFH} = V_{DDAD}$ ,  $V_{REFL} = V_{SSAD}$ ) (continued)**

| Characteristic                             | Conditions               | C | Symb                | Min | Typ <sup>1</sup> | Max  | Unit             | Comment                                                                                     |
|--------------------------------------------|--------------------------|---|---------------------|-----|------------------|------|------------------|---------------------------------------------------------------------------------------------|
| Conversion Time<br>(Including sample time) | Short Sample (ADLSMP=0)  | P | t <sub>ADC</sub>    | —   | 20               | —    | ADCK cycles      | See the ADC chapter in the <i>MCF51CN128 Reference Manual</i> for conversion time variances |
|                                            | Long Sample (ADLSMP=1)   | C |                     | —   | 40               | —    |                  |                                                                                             |
| Sample Time                                | Short Sample (ADLSMP=0)  | P | t <sub>ADS</sub>    | —   | 3.5              | —    | ADCK cycles      |                                                                                             |
|                                            | Long Sample (ADLSMP=1)   | C |                     | —   | 23.5             | —    |                  |                                                                                             |
| Total Unadjusted Error                     | 12 bit mode              | T | E <sub>TUE</sub>    | —   | ±3.0             | —    | LSB <sup>2</sup> | Includes Quantization                                                                       |
|                                            | 10 bit mode              | P |                     | —   | ±1               | ±2.5 |                  |                                                                                             |
|                                            | 8 bit mode               | T |                     | —   | ±0.5             | ±1.0 |                  |                                                                                             |
| Differential Non-Linearity                 | 12 bit mode              | T | DNL                 | —   | ±1.75            | —    | LSB <sup>2</sup> |                                                                                             |
|                                            | 10 bit mode <sup>3</sup> | P |                     | —   | ±0.5             | ±1.0 |                  |                                                                                             |
|                                            | 8 bit mode <sup>3</sup>  | T |                     | —   | ±0.3             | ±0.5 |                  |                                                                                             |
| Integral Non-Linearity                     | 12 bit mode              | T | INL                 | —   | ±1.5             | —    | LSB <sup>2</sup> |                                                                                             |
|                                            | 10 bit mode              | P |                     | —   | ±0.5             | ±1.0 |                  |                                                                                             |
|                                            | 8 bit mode               | T |                     | —   | ±0.3             | ±0.5 |                  |                                                                                             |
| Zero-Scale Error                           | 12 bit mode              | T | E <sub>ZS</sub>     | —   | ±1.5             | —    | LSB <sup>2</sup> | V <sub>ADIN</sub> = V <sub>SSAD</sub>                                                       |
|                                            | 10 bit mode              | P |                     | —   | ±0.5             | ±1.5 |                  |                                                                                             |
|                                            | 8 bit mode               | T |                     | —   | ±0.5             | ±0.5 |                  |                                                                                             |
| Full-Scale Error                           | 12 bit mode              | T | E <sub>FS</sub>     | —   | ±1.0             | —    | LSB <sup>2</sup> | V <sub>ADIN</sub> = V <sub>DDAD</sub>                                                       |
|                                            | 10 bit mode              | P |                     | —   | ±0.5             | ±1   |                  |                                                                                             |
|                                            | 8 bit mode               | T |                     | —   | ±0.5             | ±0.5 |                  |                                                                                             |
| Quantization Error                         | 12 bit mode              | D | E <sub>Q</sub>      | —   | -1 to 0          | —    | LSB <sup>2</sup> |                                                                                             |
|                                            | 10 bit mode              |   |                     | —   | —                | ±0.5 |                  |                                                                                             |
|                                            | 8 bit mode               |   |                     | —   | —                | ±0.5 |                  |                                                                                             |
| Input Leakage Error                        | 12 bit mode              | D | E <sub>IL</sub>     | —   | ±2               | —    | LSB <sup>2</sup> | Pad leakage <sup>4</sup> *<br>R <sub>AS</sub> {test=pad leakage test}                       |
|                                            | 10 bit mode              |   |                     | —   | ±0.2             | ±4   |                  |                                                                                             |
|                                            | 8 bit mode               |   |                     | —   | ±0.1             | ±1.2 |                  |                                                                                             |
| Temp Sensor Slope                          | -40°C to 25°C            | D | m                   | —   | 1.646            | —    | mV/°C            |                                                                                             |
|                                            | 25°C to 85°C             |   |                     | —   | 1.769            | —    |                  |                                                                                             |
| Temp Sensor Voltage                        | 25°C                     | D | V <sub>TEMP25</sub> | —   | 701.2            | —    | mV               |                                                                                             |

<sup>1</sup> Typical values assume  $V_{DDAD} = 3.3$  V, Temp = 25 °C,  $f_{ADCK} = 1.0$  MHz unless otherwise stated. Typical values are for reference only and are not tested in production.

<sup>2</sup> 1 LSB =  $(V_{REFH} - V_{REFL})/2^N$

<sup>3</sup> Monotonicity and No-Missing-Codes guaranteed in 10 bit and 8 bit modes

<sup>4</sup> Based on input pad leakage current. Refer to pad electricals.

### 3.12.5 Flash Specifications

This section provides details about program/erase times and program-erase endurance for the flash memory.

Program and erase operations do not require any special power sources other than the normal  $V_{DD}$  supply. For more detailed information about program/erase operations, see the Memory section of the *MCF51CN128 Reference Manual*.

**Table 22. Flash Characteristics**

| C | Characteristic                                                                         | Symbol                  | Min         | Typical      | Max    | Unit              |
|---|----------------------------------------------------------------------------------------|-------------------------|-------------|--------------|--------|-------------------|
| D | Supply voltage for program/erase<br>-40 °C to 85 °C                                    | $V_{\text{prog/erase}}$ | 1.8         | —            | 3.6    | V                 |
| D | Supply voltage for read operation                                                      | $V_{\text{Read}}$       | 1.8         | —            | 3.6    | V                 |
| D | Internal FCLK frequency <sup>1</sup>                                                   | $f_{\text{FCLK}}$       | 150         | —            | 200    | kHz               |
| D | Internal FCLK period (1/FCLK)                                                          | $t_{\text{Fcyc}}$       | 5           | —            | 6.67   | μs                |
| P | Longword program time (random location) <sup>(2)</sup>                                 | $t_{\text{prog}}$       | 9           |              |        | $t_{\text{Fcyc}}$ |
| P | Longword program time (burst mode) <sup>(2)</sup>                                      | $t_{\text{Burst}}$      | 4           |              |        | $t_{\text{Fcyc}}$ |
| P | Page erase time <sup>2</sup>                                                           | $t_{\text{Page}}$       | 4000        |              |        | $t_{\text{Fcyc}}$ |
| P | Mass erase time <sup>(2)</sup>                                                         | $t_{\text{Mass}}$       | 20,000      |              |        | $t_{\text{Fcyc}}$ |
| D | Longword program current <sup>3</sup>                                                  | $R_{\text{IDDBP}}$      | —           | 9.7          | —      | mA                |
| D | Page erase current <sup>3</sup>                                                        | $R_{\text{IDDPE}}$      | —           | 7.6          | —      | mA                |
| C | Program/erase endurance <sup>4</sup><br>$T_L$ to $T_H$ = -40°C to + 85°C<br>$T$ = 25°C |                         | 10,000<br>— | —<br>100,000 | —<br>— | cycles            |
| C | Data retention <sup>5</sup>                                                            | $t_{\text{D\_ret}}$     | 15          | 100          | —      | years             |

<sup>1</sup> The frequency of this clock is controlled by a software setting.

<sup>2</sup> These values are hardware state machine controlled. User code does not need to count cycles. This information supplied for calculating approximate time to program and erase.

<sup>3</sup> The program and erase currents are additional to the standard run  $I_{DD}$ . These values are measured at room temperatures with  $V_{DD}$  = 3.3 V, bus frequency = 8.0 MHz.

<sup>4</sup> **Typical endurance for flash** was evaluated for this product family on the HC9S12Dx64. For additional information on how Freescale defines typical endurance, please refer to Engineering Bulletin EB619, *Typical Endurance for Nonvolatile Memory*.

<sup>5</sup> **Typical data retention** values are based on intrinsic capability of the technology measured at high temperature and de-rated to 25 °C using the Arrhenius equation. For additional information on how Freescale defines typical data retention, refer to Engineering Bulletin EB618, *Typical Data Retention for Nonvolatile Memory*.

### 3.13 EMC Performance

Electromagnetic compatibility (EMC) performance is highly dependent on the environment in which the MCU resides. Board design and layout, circuit topology choices, location and characteristics of external components as well as MCU software operation all play a significant role in EMC performance. The system designer should consult Freescale applications notes such as AN2321, AN1050, AN1263, AN2764, and AN1259 for advice and guidance specifically targeted at optimizing EMC performance.

### 3.13.1 Radiated Emissions

Microcontroller radiated RF emissions are measured from 150 kHz to 1 GHz using the TEM/GTEM Cell method in accordance with the IEC 61967-2 and SAE J1752/3 standards. The measurement is performed with the microcontroller installed on a custom EMC evaluation board while running specialized EMC test software. The radiated emissions from the microcontroller are measured in a TEM cell in two package orientations (North and East). For more detailed information concerning the evaluation results, conditions and setup, please refer to the EMC Evaluation Report for this device.

## 4 Ordering Information

This section contains ordering information for MCF51CN128 devices.

**Table 23. Ordering Information**

| Freescale Part Number <sup>1</sup> | Memory |     | Temperature Range (°C) | Package <sup>2</sup> |
|------------------------------------|--------|-----|------------------------|----------------------|
|                                    | Flash  | RAM |                        |                      |
| MCF51CN128CLK                      | 128K   | 24K | –40 to +85             | 80-pin LQFP          |
| MCF51CN128CLH                      | 128K   | 24K | –40 to +85             | 64-pin LQFP          |
| MCF51CN128CGT                      | 128K   | 24K | –40 to +85             | 48-pin QFN           |

<sup>1</sup> See the *MCF51CN128 Reference Manual* (document MCF51CN128RM), for a complete description of modules included on each device.

<sup>2</sup> See [Table 24](#) for package information.

## 5 Package Information

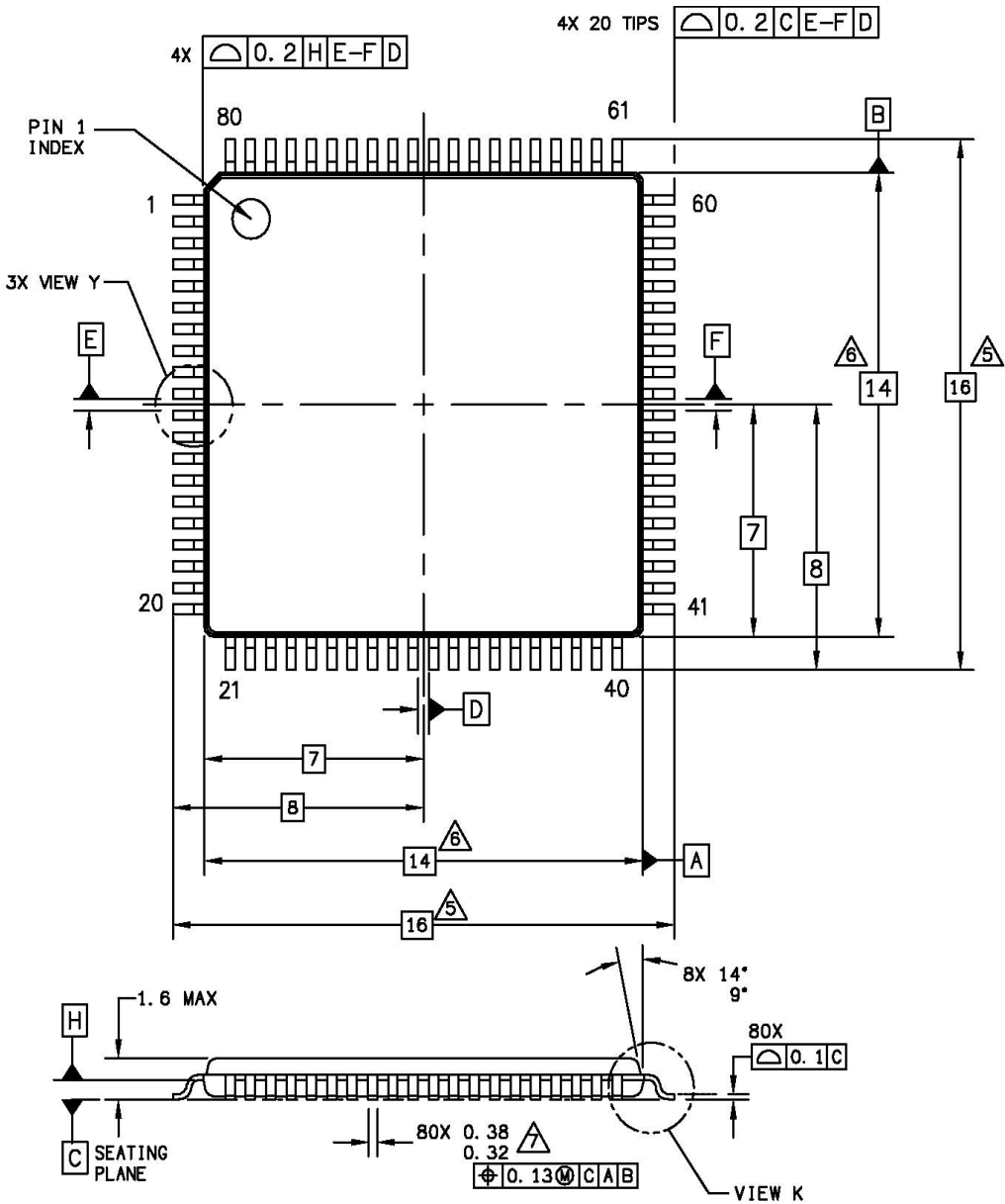
**Table 24. Package Descriptions**

| Pin Count | Package Type          | Abbreviation | Designator | Case No. | Document No. |
|-----------|-----------------------|--------------|------------|----------|--------------|
| 80        | Low Quad Flat Package | LQFP         | LK         | 917A     | 98ASS23237W  |
| 64        | Low Quad Flat Package | LQFP         | LH         | 840F     | 98ASS23234W  |
| 48        | Quad Flat No-Leads    | QFN          | GT         | 1314     | 98ARH99048A  |

## 6 Mechanical Outline Drawings

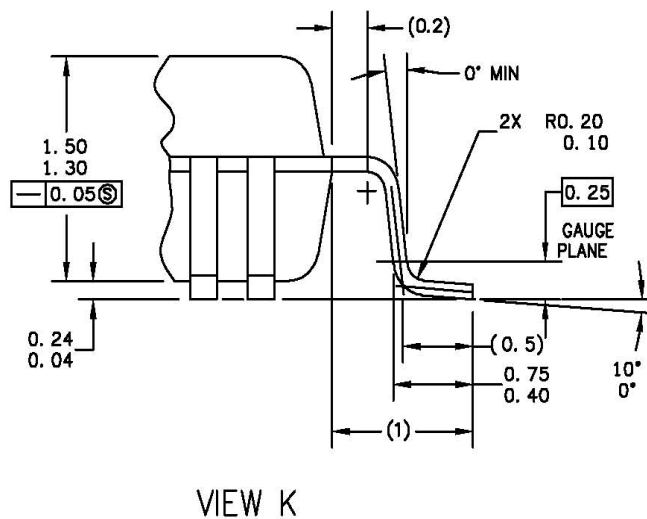
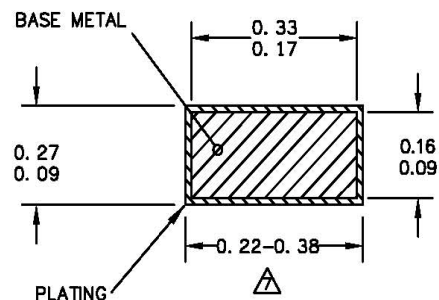
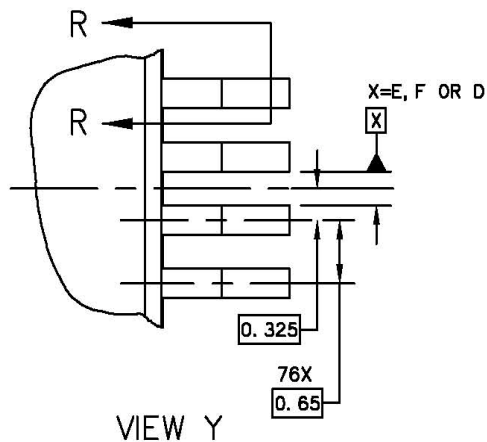
The following pages are mechanical drawings for the packages described in [Table 24](#). For the latest available drawings, visit freescale web site (<http://www.freescale.com>) and enter the package's document number into the keyword search box.

# 6.1 80-pin LQFP



|                                                                |                           |                            |
|----------------------------------------------------------------|---------------------------|----------------------------|
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| TITLE:<br>80 LD LQFP, 14 X 14 PKG,<br>0.65 MM PITCH, 1.4 THICK | DOCUMENT NO: 98ASS23237W  | REV: E                     |
|                                                                | CASE NUMBER: 917A-03      | 28 APR 2006                |
|                                                                | STANDARD: NON-JEDEC       |                            |

# Mechanical Outline Drawings



|                                                                |  |                          |  |                            |  |
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|                                                                |  | CASE NUMBER: 917A-03     |  | 28 APR 2006                |  |
|                                                                |  | STANDARD: NON-JEDEC      |  |                            |  |

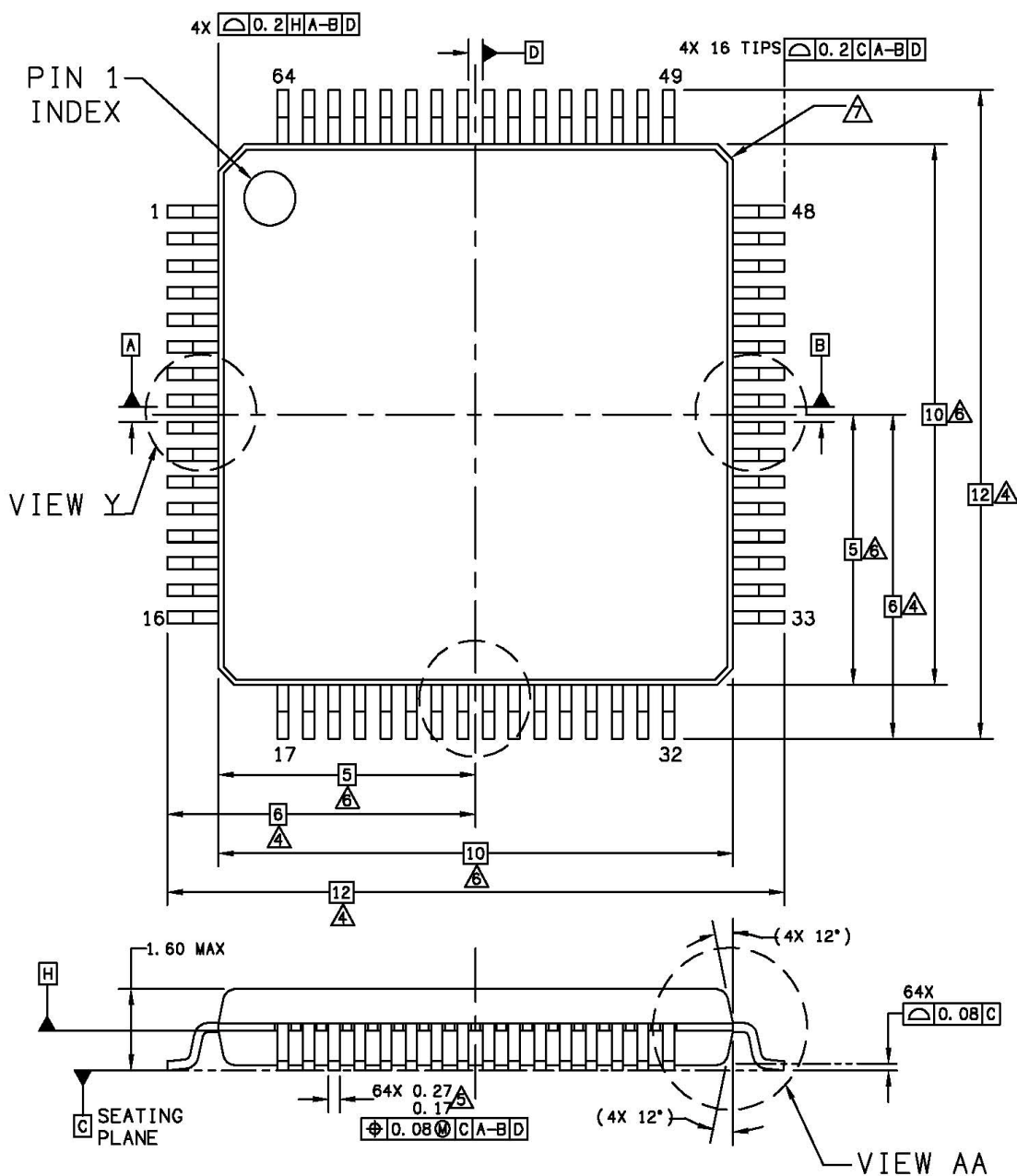


NOTES:

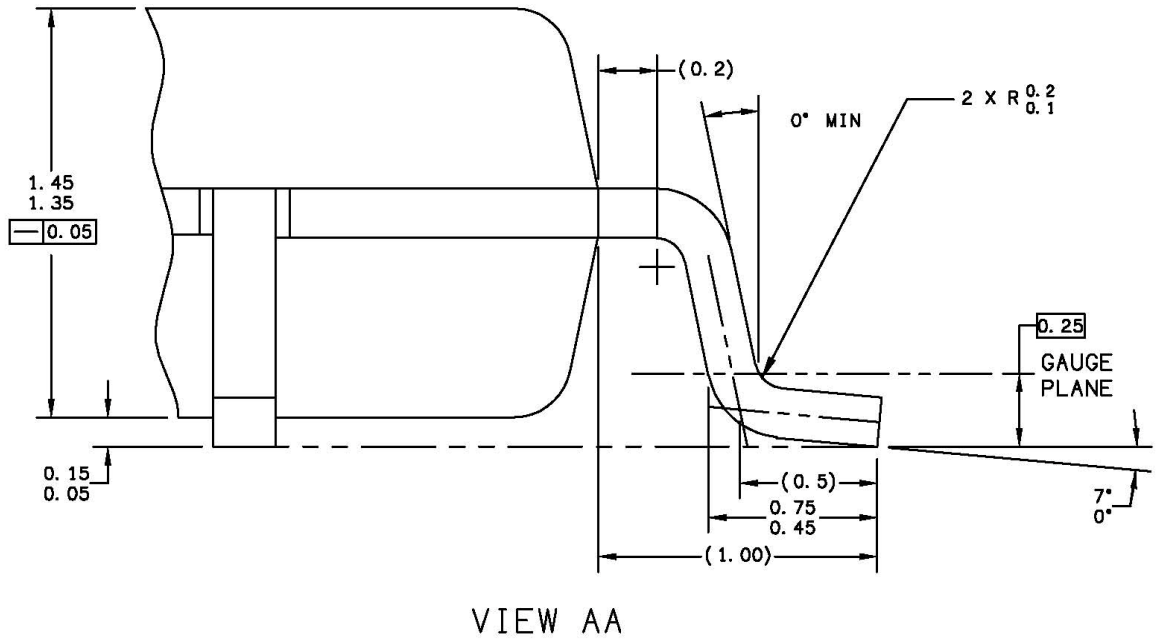
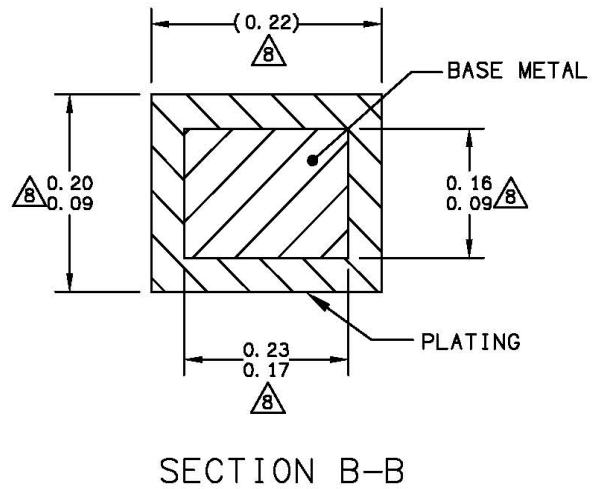
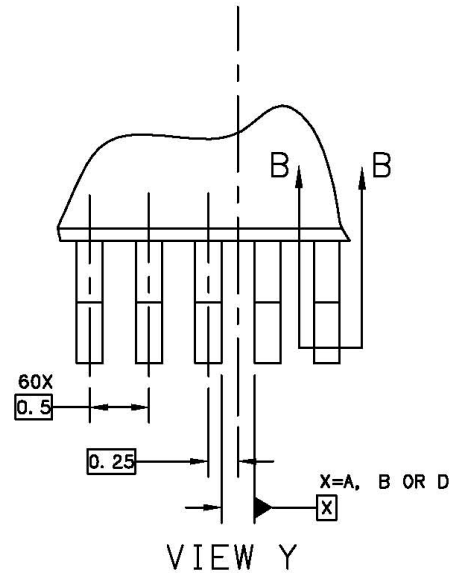
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
2. CONTROLLING DIMENSION : MILIMETER.
3. DATUM PLANE H IS LOCATED AT THE BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
4. DATUM E, F AND D TO BE DETERMINED AT DATUM PLANE H.
5. DIMENSIONS TO BE DETERMINED AT SEATING PLANE C.
6. DIMENSIONS DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 PER SIDE. DIMENSIONS DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE H.
7. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED 0.46. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD OR PROTRUSION 0.07.

|                                                                |                           |                            |             |
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| TITLE:<br>80 LD LQFP, 14 X 14 PKG,<br>0.65 MM PITCH, 1.4 THICK | DOCUMENT NO: 98ASS23237W  |                            | REV: E      |
|                                                                | CASE NUMBER: 917A-03      |                            | 28 APR 2006 |
|                                                                | STANDARD: NON-JEDEC       |                            |             |

## 6.2 64-pin LQFP



|                                                                                                                                                    |                            |  |                            |
|----------------------------------------------------------------------------------------------------------------------------------------------------|----------------------------|--|----------------------------|
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|                                                                                                                                                    | DOCUMENT NO: 98ASS23234W   |  | REV: E                     |
|                                                                                                                                                    | CASE NUMBER: 840F-02       |  | 11 AUG 2006                |
|                                                                                                                                                    | STANDARD: JEDEC MS-026 BCD |  |                            |



|                                                                       |  |                            |  |                            |  |
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| TITLE:<br>64LD LQFP,<br>10 X 10 X 1.4 PKG,<br>0.5 PITCH, CASE OUTLINE |  | DOCUMENT NO: 98ASS23234W   |  | REV: E                     |  |
|                                                                       |  | CASE NUMBER: 840F-02       |  | 11 AUG 2006                |  |
|                                                                       |  | STANDARD: JEDEC MS-026 BCD |  |                            |  |

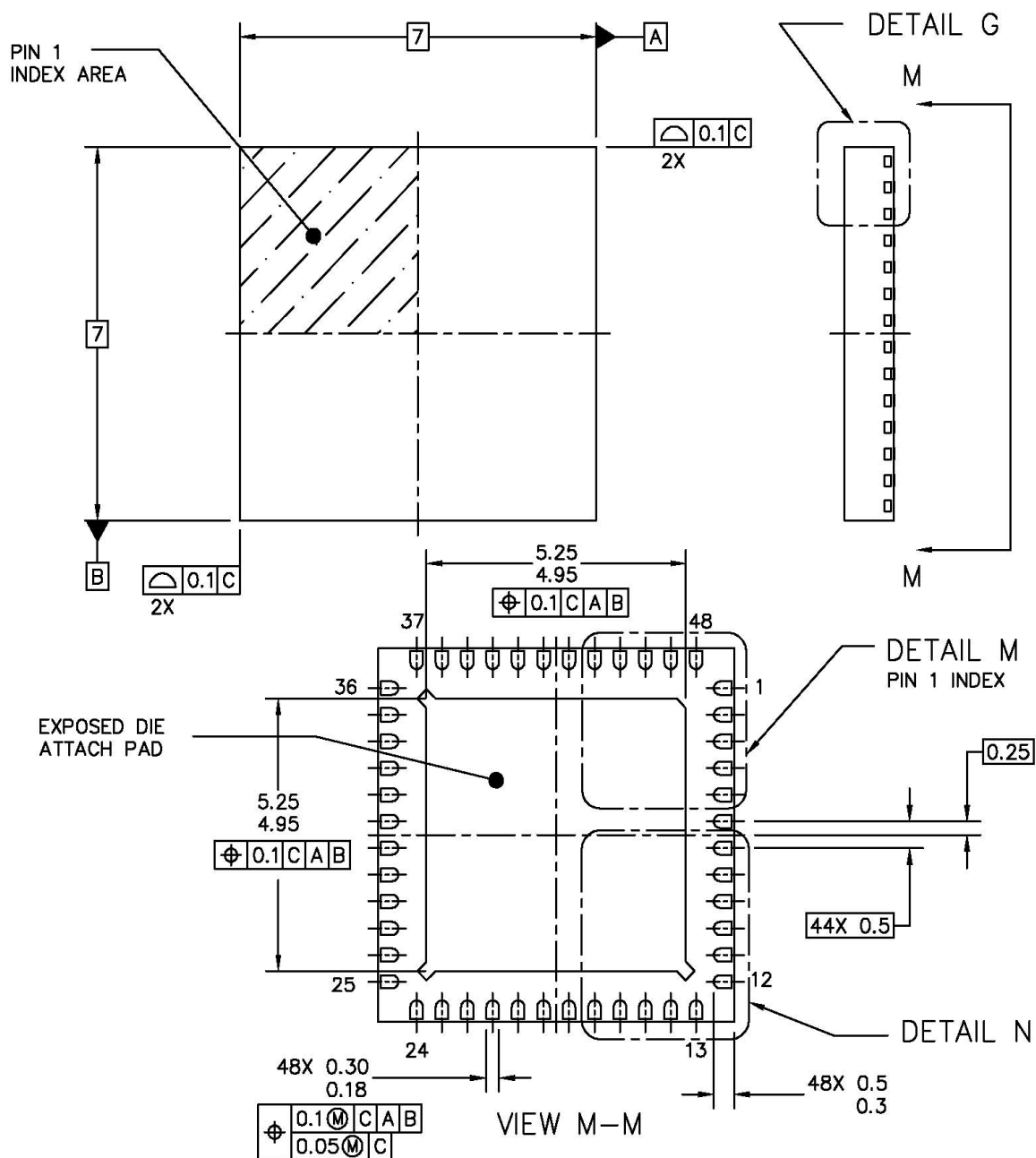
## Mechanical Outline Drawings

### NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
4. DIMENSIONS TO BE DETERMINED AT SEATING PLANE C.
5. THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED THE UPPER LIMIT BY MORE THAN 0.08 mm AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD SHALL NOT BE LESS THAN 0.07 mm.
6. THIS DIMENSION DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 mm PER SIDE. THIS DIMENSION IS MAXIMUM PLASTIC BODY SIZE DIMENSION INCLUDING MOLD MISMATCH.
7. EXACT SHAPE OF EACH CORNER IS OPTIONAL.
8. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.1 mm AND 0.25 mm FROM THE LEAD TIP.

|                                                                       |  |                            |  |                            |  |
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| TITLE:<br>64LD LQFP,<br>10 X 10 X 1.4 PKG,<br>0.5 PITCH, CASE OUTLINE |  | DOCUMENT NO: 98ASS23234W   |  | REV: E                     |  |
|                                                                       |  | CASE NUMBER: 840F-02       |  | 11 AUG 2006                |  |
|                                                                       |  | STANDARD: JEDEC MS-026 BCD |  |                            |  |

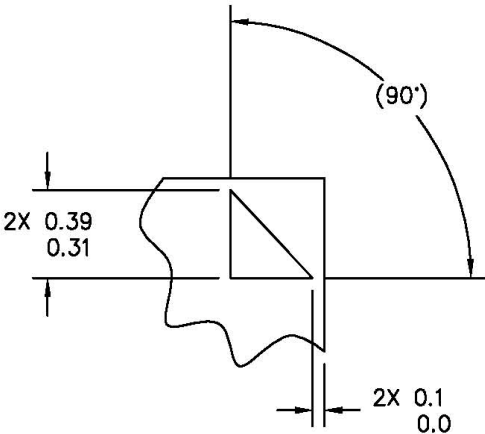
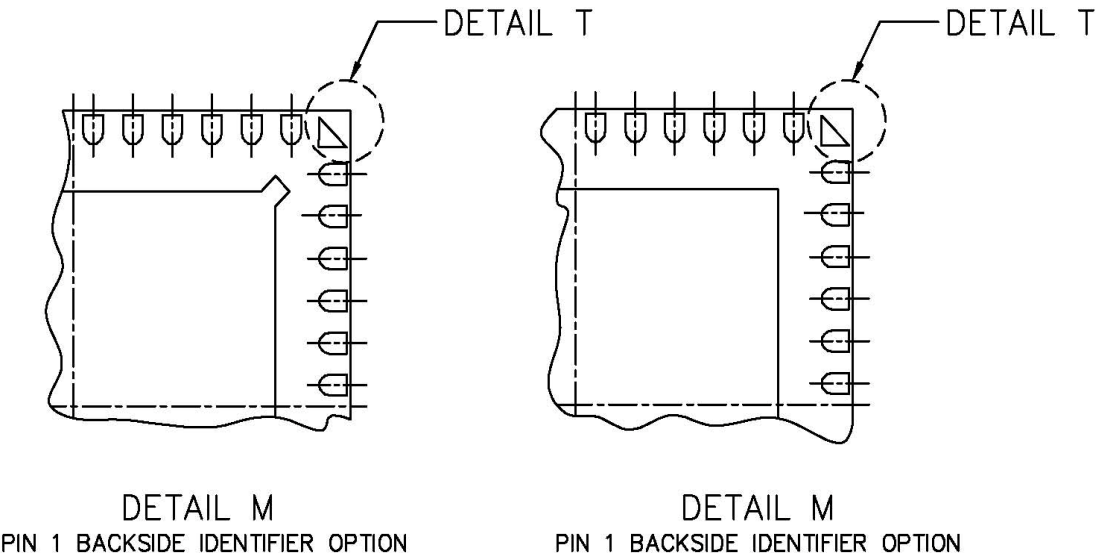
### 6.3 48-pin QFN



|                                                                                                       |  |                           |                               |                            |             |
|-------------------------------------------------------------------------------------------------------|--|---------------------------|-------------------------------|----------------------------|-------------|
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| TITLE: THERMALLY ENHANCED QUAD<br>FLAT NON-LEADED PACKAGE (QFN)<br>48 TERMINAL, 0.5 PITCH (7 X 7 X 1) |  |                           | DOCUMENT NO: 98ARH99048A      |                            | REV: F      |
|                                                                                                       |  |                           | CASE NUMBER: 1314-05          |                            | 05 DEC 2005 |
|                                                                                                       |  |                           | STANDARD: JEDEC-MO-220 VKKD-2 |                            |             |



|                                                                                                       |  |                           |                               |                            |             |
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| TITLE: THERMALLY ENHANCED QUAD<br>FLAT NON-LEADED PACKAGE (QFN)<br>48 TERMINAL, 0.5 PITCH (7 X 7 X 1) |  |                           | DOCUMENT NO: 98ARH99048A      |                            | REV: F      |
|                                                                                                       |  |                           | CASE NUMBER: 1314-05          |                            | 05 DEC 2005 |
|                                                                                                       |  |                           | STANDARD: JEDEC-MO-220 VKKD-2 |                            |             |



|                                                         |                                                                                                       |  |                            |             |
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|                                                         | TITLE: THERMALLY ENHANCED QUAD<br>FLAT NON-LEADED PACKAGE (QFN)<br>48 TERMINAL, 0.5 PITCH (7 X 7 X 1) |  | DOCUMENT NO: 98ARH99048A   | REV: F      |
|                                                         |                                                                                                       |  | CASE NUMBER: 1314-05       | 05 DEC 2005 |
|                                                         | STANDARD: JEDEC-MO-220 VKKD-2                                                                         |  |                            |             |

**Mechanical Outline Drawings**

NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M–1994.
3. THE COMPLETE JEDEC DESIGNATOR FOR THIS PACKAGE IS: HF–PQFN.
4.  COPLANARITY APPLIES TO LEADS, CORNER LEADS, AND DIE ATTACH PAD.
5. MIN METAL GAP SHOULD BE 0.2MM.

|                                                                                                       |                               |                            |             |
|-------------------------------------------------------------------------------------------------------|-------------------------------|----------------------------|-------------|
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|                                                                                                       | CASE NUMBER: 1314–05          |                            | 05 DEC 2005 |
|                                                                                                       | STANDARD: JEDEC–MO–220 VKKD–2 |                            |             |



# 7 Revision History

This section lists the changes between versions of MCF51CN128 Data Sheet document.

**Table 25. Revision History**

| Revision Number | Date         | Description of Changes                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                          |
|-----------------|--------------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 1               | August 2008  | Alpha Customer Release.                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                         |
| 2               | January 2009 | Pre-Launch Release.                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                             |
| 3               | January 2009 | Launch Release.                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                 |
| 4               | May 2009     | <ul style="list-style-type: none"> <li>Changed LVDH trip and recovery values in <a href="#">Table 8</a>.</li> <li>Fixed Mini-FlexBus maximum frequency to 25.1666 MHz in <a href="#">Section 3.10, "Mini-FlexBus Timing Specifications."</a></li> <li>Updated FEC feature list to describe ethernet operation between 3.0 V to 3.6 V.</li> <li>In <a href="#">Table 8</a>, added a footnote to the operating voltage. It describes an exception to the Fast Ethernet Controller (FEC), because it is only operational above the operating voltage of 3 V.</li> <li>Corrected Freescale part numbers in <a href="#">Table 23</a>.</li> <li>In <a href="#">Table 21</a>, changed I<sub>DDAD</sub> classification to T.</li> </ul> |

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